Module Platform Solution Guide

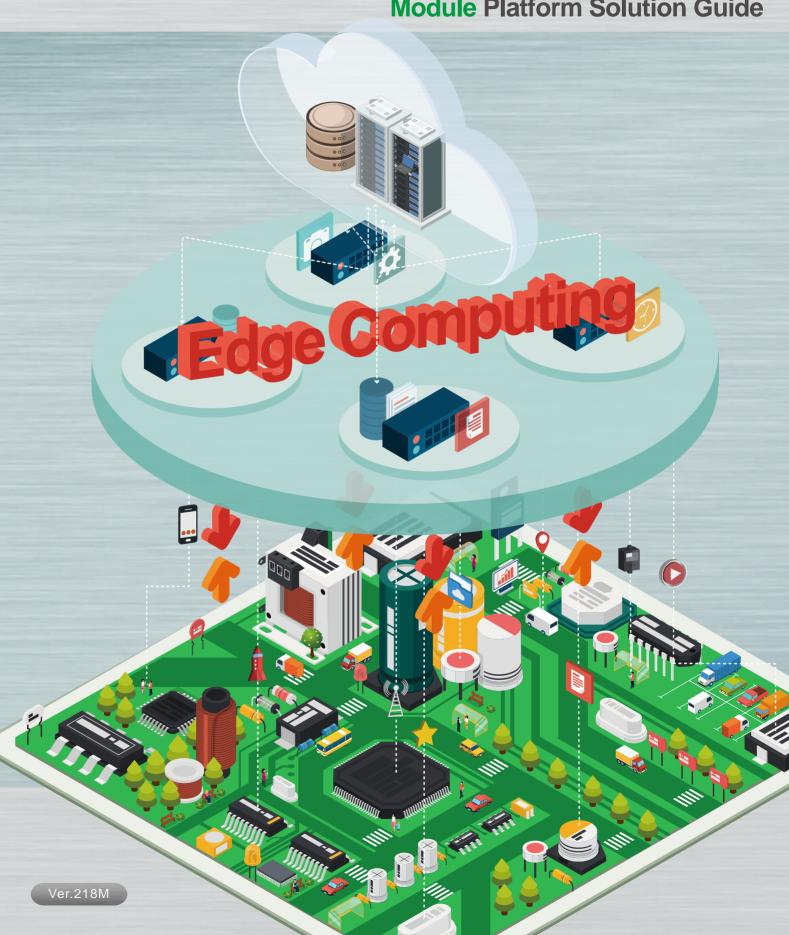




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COMPUTER OF MODULE

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Intel® Atom™ E3800 series SoC based on Type 10 Mini COM Express® module with DDR3L SDRAM, NANDrive, DDI support, and USB3.0



13-14 PCOM-BA01

Intel® Atom™ E3900 series SoC based on Type 10 Mini COM Express® Rev3.0 module with DDR3L SDRAM,eMMC, DDI support, and USB3.0



15-16 PCOM-B632VG

Intel® Atom™ E3800 series SoC based on Type 6 COM Express® module with DDR3L SO-DIMM sockets,VGA, eDP, DDI, GbE, and SATA 3 Gb/s



17-18 PCOM-B634VG

Intel® Pentium® / Xeon® D-1500 series Processor based on Type 6 COM Express® 2.0 module with DDR4 ECC/Non-ECC 3x SO-DIMM sockets, VGA, DDI, PClex 16, 10GbE, USB 3.0, and SATA 6 Gb/s



19-20 PCOM-B637VG

Intel[®] 6th Generation Core[™] Skylake / Kabylake-S processors based on Type VI Compact-COM Express 2.0 module with DDR4 SDRAM on Two SO-DIMM slots, VGA, eDP, DP, Gigabit Ethernet, PCIE, SATA and USB



21-22 PCOM-B638VG

Intel® Kabylake-U/Skylake-U Core™ i7/i5/i3 processor based on Type VI Compact-COM Express 2.0 module with DDR4 SDRAM on SO-DIMM slots, VGA, LVDS, Display-port, Gigabit Ethernet, PCIE, SATA, USB, and OTG



23-24 PCOM-B639VG

Intel® Core™ Kabylake-H/Skylake-H Processor based on Type VI COM Express module with DDR4 SDRAM, VGA, LVDS, Gigabit Ethernet, SATA 3.0 and USB



25-26 PCOM-B641VG

Intel® Atom™ E3900 series SoC based on Type 6 COM Express® Rev3.0 module with DDR3L 2x SO-DIMM sockets, VGA, eDP/LVDS, DDI, GbE, and SATA 6 Gb/s



27-28 PCOM-B700G

Intel® Pentium® / Xeon® D-1500 series Processor based on Type 7 COM Express® Rev3.0 module with DDR4 ECC/Non-ECC 3x SO-DIMM sockets, 1x PCle 3.0 x16, 1x PCle 3.0 x4, and 8x PCle 2.0 x1, TPM 2.0, and 2x KRx1, TPM 2.0, and 2x KR



29-30 PCOM-B701G

Intel® C3000 series Processor based on Type 7 COM Express® Rev3.0 module with DDR4 ECC/Non-ECC 3x SO-DIMM sockets, 20x PCIe Lanes, 4x KR/KX, GbE, NC-SI, TPM 2.0, and SATA 6 Gb/s



31-32 PCOM-C640

PCOM-C640 is NANO-ITX carrier board with triple display, Gigabit Ethernet, Audio, USB 3.0, SATA. It's a powerful carrier which is suitable for system

5 Intellegence

6 Technology

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33-34 PCOM-C605

PCOM-C605 is Mini-ITX Form Factor Evaluation Carrier Board COMExpress Revision 2.0 Type VI Module



35-36 PCOM-C700G

ATX Form Factor Evaluation Carrier Board for Type 7 COM Express® Rev3.0 module with 4x 10GbE Support



37-38 PQ7-M106

Qseven Module Based on Intel® Atom™ Processor E3800 Series with DDR3L SDRAM up to 8GB. LVDS/eDP and eMMC



39-40 PQ7-M108

Qseven module by Qseven 2.1 based on Intel® Atom™ / Pentium® / Celeron® processors ("Apollo Lake") with LPDDR4 SDRAM up to 8GB, 24bit LVDS, DP/HDMI



41-42 PEM-E203VLA

Intel® ATOM® E3800 series processor based on form factormodule ETX® 3.0 specification with DDR3 optional ECC/Non-ECC Memory down, VGA, LVDS, Gigabit Ethernet, IDE,PCI, ISA, Parallel Port, SATA and USB



43-44 PEM-E205VLA

Vortex DX3 processor based on ETX 3.02 module with DDR3 Memory down, VGA, LVDS, PCI, ISA, IDE and USB



45-46 PSMC-M1011

SMARC module by SMARC 2.0 based on Intel® Atom™ / Pentium® / Celeron® processors ("Apollo Lake") with LPDDR4 SDRAM up to 8GB, 24bit LVDS, DP, HDMI

- 47 Signal integrity is tested and assured
- Power & energy use confirmed stable and efficient
- 49 Our modules are resistant to rapidly changing electrical currents
- Our modules are compliant with EMS standards
- A farm of chambers for module testing
- 52 Bringing thermal validation expertise
- to module development
- 53 Silence is a signature of our modules
- The noise emission meet ISO Standards
- 55 Breaking the module to be stronger
- 56 Super-aging our modules to unveil weaknesses
- 57 Undergo shipping simulation to ensure intact transportation
- 58 Portwell superior service

About Portwell

Portwell, Inc. was founded in 1993 and entered the Industrial PC market in 1995 by developing single-board computers. Today, our continuous development of leading-edge products has resulted in strong growth in market shares and revenue, a firm place on the Taipei stock exchange (TAISDAQ), and has established Portwell as a major worldwide supplier of specialty computing application platforms and services. Portwell, Inc. is a Premier member of the Intel® Internet of Things Solutions Alliance. From modular components to market-ready systems, Intel and the 250+ global member companies of the Intel® Internet of Things

Solutions Alliance provide scalable, interoperable solutions that accelerate deployment of intelligent devices and end-to-end analytics. Portwell, Inc. is also a member of the selected group of Intel® Applied Computing Platform Providers (IACPP), as well as Advanced Telecom Computing Architecture (ATCA) and an executive member of PCI Industrial Computer Manufacturing group (PICMG).



Portwell, Inc. has worldwide operations in the U.S.A., Taiwan, Japan, China, Netherlands, United Kingdom, Germany, Latin America and India. Whether you are working on a computer board or turnkey system, Portwell is the perfect partner to help you deliver your products to the market on time as well as maintain longevity of product. With 20 years experience in the design and manufacturing of specialty computer boards and systems, Portwell not only provides a one-stop resource for off-the-shelf products, but also supplies custom-built solutions and a global logistics services to suit your needs.

Portwell OEM and ODM solutions satisfy your needs in retail automation, medical equipment, industrial automation, infotainment,

communication, and network security markets. Encouraged by our flexible business support, manufacturing excellence, and compliance with high quality and environmental standards such as ISO 9001/14000/13485, OHSAS and RoHS, customers have taken advantage of our dedicated and sophisticated engineering resource to satisfy their requirements for the design, manufacturing and logistics of application-specific computer boards, customized computer chassis, and specific computer system configurations. Whether you are working on a Medical Single Board Computer or Internet Security Appliance, Portwell is, again, the perfect partner to help you deliver your products to the market on time and stay one step ahead of the competition.













Focus on your core competencies

Design for Extreme Reliability Time To Market



Baseboard — SAFE, RELIABLE, SECURE

Portwell designs competence for your market! As a worldwide technology leader in the embedded industry and also a leading outsourcing partner for OEMs in different markets, Portwell's boards can give you the most dependable, powerful and economic basis to meet your carrier board design. You may take a big step forward into a successful future with our proactive project management and ISO 9001:2000 certificate. Portwell provides onestop shopping so that you can get to the markets faster with complete assemblies including housings and keep your products available for many years with life cycle management.

Module — Solutions That Grow With You

The CPU module delivers the core functionality while all of the application-specific features are designed into the baseboard creating a semi-custom embedded PC solution.

How to enable faster time-to-market and cost-effective customization alternatives? COM (Computer-On-Module) is the answer.

COMs are not only highly integrated component SBCs that support system expansion and application-specific customizations but also improving form, fit and function, minimizing current and future design risks. As well as providing lower product lifecycle costs through module scalability and interchangeability.

Module

Computer-On-Module

Various off-the-shelf core module with additional functionality that is required for specific applications



COM-Express® —

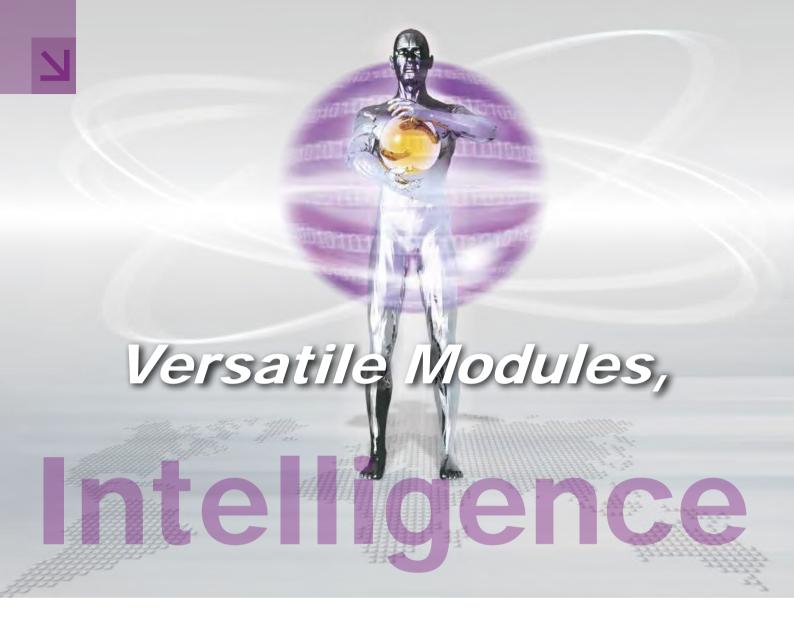
COM Express® defines standardized form factors and pinouts for Computer-on-Modules. The standard includes the mini form factor (84 x 55mm), the compact form factor (95 x 95mm) and the basic form factor (125 x 95mm). To serve industry requirements, the Digital Display Interfaces (DisplayPort, HDMI) and super-fast USB 3.0 were recently added to the pin-out definitions for COM Express® modules.

Qseven® -

This standard platform has been developed with performance and flexibility in mind, allowing various processor configurations to maximize passive cooling technology. With a maximum power consumption of around 12W specified in the standard, the new form factor is expected to appeal to manufacturers of applications that require fanless operation.

SMARC-

The SMARC ("Smart Mobility ARChitecture") is a versatile small form factor computer Module definition targeting applications that require low power, low costs, and high performance. Module sizes are defined: 82mm x 50mm and 82mm x 80mm with 314 edge fingers that mate with a low profile 314 pin 0.5mm pitch right angle connector.



What Portwell distributed Intelligence?

Portwell provides remote technology to oversee the world. Portwell distributed intelligence is essential for increasing the capabilities – Remote diagnostic and repair , helping to increase equipment availability. Software reliability by isolating application code and helping to prevent dangerous interactions and security by preventing any node from executing malicious software.

Start-Up Intelligent Technology by Portwell Computer-On-Module Solution

With energy demand growing, the smart grid provides opportunities for utility operators to transform their electrical networks. By using Portwell technologies, which provide higher levels of scalability, performance, energy-efficiency and serviceability, next-generation equipment can offer utilities improved energy management and lower operating costs.



Flexible and Scalable Modular Platforms

Each element on the grid will demand a particular set of features; however, most elements can often be designed using a single-processor architecture with exceptional scalability, upgradeability and flexibility.

- Large processor selection: With a wide choice of processors, it's straightforward to scale designs to meet the right price-performance.
- Single code base: Equipment manufacturers can easily upgrade designs when the processor family is completely code compatible.
- I/O flexibility: Open modular systems, supporting multiple standard busses, allow designers to satisfy a wide range of I/O requirements.
- Reliable supplier: Chip manufacturers, with a reputation for delivering long life cycle products, help preserve equipment manufacturers' development investments.

Easy to increase Embedded Computing Requirements

Regulatory and market realities are requiring a new way of thinking for utilities, and the use of standards-based building blocks to build out the grid will drive greater plant efficiency, higher renewable energy production and more advanced conservation programs.



PCOM Interface

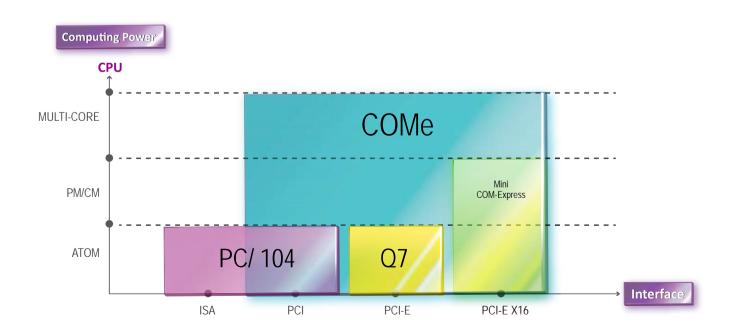
COM Express® specification adopted in July, 2005, redefined electrical, mechanical and thermal requirements for a highly integrated Computer On Module (COM) supporting rich combinations of high-speed I/O interfaces while keeping key legacy interface technologies enabling a smooth migration of interface technologies at once. The primary new technology behind COM Express® R3.0 is the support of a few new interfaces such as USB 3.0 and Digital Display Interfaces (DDI). The new technology also provides additional PCI Express lanes, high definition audio, and SPI for BIOS access. The new PCOM Interface has additional pin definitions such as Pulse Width Modulation (PWM) for fan control and TPM support for security and management. The evolution of the PCOM Module has adopted a Mini module of 84 x 55mm which is also more energy efficient under 12W.

Naming Guide - Line of Portwell Com Express

| PCOM Series | PCOM | | Portwell COM Express |
|----------------------|----------------|---|--------------------------------|
| Carrier or Module | X ₁ | В | Module Board, Portwell Design |
| | | С | Carrier board, Portwell Desing |
| COM Express Pin Type | X ₂ | 1 | Type 1 Pin-Out |
| | | 2 | Type 2 Pin-Out |
| | | 3 | Type 3 Pin-Out |
| | | 4 | Type 4 Pin-Out |
| | | 5 | Type 5 Pin-Out |
| | | 6 | Type 6 Pin-Out |
| | | 7 | Type 7 Pin-Out |
| | | Α | Type 10 Pin-Out |

| PCOM Series | PCOM | | Portwell COM Express |
|-------------------------|--------------------------------|-----|----------------------|
| Seriial Number | X ₃ ~X ₄ | 0-9 | TBD |
| VGA support | Y ₅ | V | VGA support |
| | | L | LVDS support |
| Ethernet | Y ₆ | G | Gigabit Ethernet |
| | · | L | Fast Ethernet |
| TPM support | Y ₇ | Т | TPM support |
| Customized abbreviation | YY | | |

EX: PCOM-X₁X₂X₃X₄Y₅Y₆Y₇-YY



COM Express® Standard

| Types | Connector Rows | PCI Express | PEG | SATA Ports | LAN Ports | USB 2.0 Ports | USB 3.0 Ports | Display Interface |
|---------|-------------------|----------------|-----|---------------|--------------------|------------------|------------------|----------------------------------|
| Type 6 | AB & CD | Up to 24 | 1 | 4 | 1x GbE | 8 | 4 | VGA LVDS/eDP PEG 3x DDI |
| Type 7 | AB & CD | Up to 32 | NA | 2 | 1x GbE 4x 10GbE | 4 | 4 | NA |
| Type 10 | AB | Up to 4 | NA | 2 | 1x GbE | 8 | 2 | LVDS/eDP 1x DDI |

System I/O

PCI-E Lanes LVDS/VGA
Serial TV-Out/DDI
SATA/SAS Express Card
USB 2.0 HDA
LAN LPC

System I/O

PCI-E Lanes PATA Port
PCI-E Graphics (PEG) LAN Port
SDVO DDI Interface
PCI Bus USB 3.0

System Management

SDIO Watchdog Timer
GPIO Speaker Out
SMBUS Reset
I2C

Power Management

Thermal Protection Power Button
Low Battery Alarm Sleep/Lid Input
Suspend/Wake Signals Fan Control
Optimal Power TPM
VCC_5V_SBY Contacts

Power

VCC_12V Contacts





PCOM Solution Guide













| | PCOM-BA00 | PCOM-BA01 | PCOM-B632VG | PCOM-B634VG | PCOM-B637 | PCOM-B638 |
|-------------------------|--|---|---|---|---|--|
| Form Factor (mm) | COM Express® Mini (84 x 55mm) | COM Express® Mini (84 x 55mm) | COM Express® Compact (95 x 95mm) | COM Express® Basic (125 x 95mm) | COM Express® Basic (125 x 95mm) | COM Express® Compact (95 x 95mm) |
| · · · | , | , | , | , | , | , , |
| COM Type | Type 10 | Type 10 | Type 6 | Type 6 | Type 6 | Type 6 |
| CPU/ Clock/ Cache | * Intel® E3845/ E3827/ E3825/ E3815 * 1.33 GHz to 1.91GHz * 1MB to 2MB cache | * Intel® E3950/ E3940/E3930/ N4200/N3350 * 1.1 GHz to 1.6GHz * 2MB cache | * Intel® E3845/ E3827/E3826/ E3825/E3815 * 1.33GHz up to 1.91GHz * 1MB to 2MB cache | * Intel® Xeon® D Processor * D1577/D1548/ D1539/D1527/ D1519/D1517/ D1508 * Up to 16 CPU Cores * 12M L2 Cache | * Intel® 6th Generation CoreTM 35W Desktop processor * i7-6700TE/i5- 6500TE/i3- 6100TE * Up to 4 CPU cores * 3MB to 8MB cache | * Intel® 6th Generation Core™ ULT * Intel® Celeron® 3955U/ i3-6100U/ i5-6300U/ i7- 6600U * Up to 2 CPU cores * 2MB to 4MB cache |
| Chipset | SoC | SoC | SoC | SoC | Q170/H110/C236 | SoC |
| Memory | * DDR3L 1067/1333 MT/s * Non-ECC/ ECC * Single Channel | * LPDDR4 2133 MT/s * Non-ECC * Dual Channel | * DDR3L 1067/1333 MT/s * Non-ECC * Single Channel | * DDR4 2400 MT/s * 3 SO-DIMM Sockets * Non-ECC/ ECC * Dual Channel | * DDR4 2133 MT/s * Non-ECC/ECC * Dual Channel | * DDR4 2133 MT/s Non-ECC * Dual Channel |
| USB | 1x USB 3.0 4x USB 2.0 | 2x USB 3.0 8x USB 2.0 OTG x 1 port (Optional) | 1x USB 3.0 4x USB 2.0 | 4x USB 3.0 7x USB 2.0 | 4 x USB 3.0 8 x USB 2.0 | 3 x USB 3.0 8 x USB 2.0 (One Optional OTG) |
| PCI Express | 3x PCIe 2.0 x1 (Optional to 4 x PCIe x1) | 4x PCle 2.0 x1 | 3x PCle 2.0 x1 | 1x PCle 3.0 x16 8x PCle 2.0 x1 | 1 x PCle 3.0 x16 8 x PCle 3.0 x1 | 1 x PCle 3.0 x4 5 x PCle 3.0 x1 |
| Ethernet | LAN I210-IT | LAN I210-IT | LAN I210IT | Intel® I210IT 2x KR(10GbE) | Intel® I219LM | Intel® I219LM |
| Sound | Intel® High Definition Audio | Intel® High Definition Audio | Intel® High Definition Audio | TPM 2.0 (Option) | Intel® High Definition Audio | Intel® High Definition Audio |
| Graphic Controller | Intel [®] HD Graphic | * Intel® HD Graphics 505 * Intel® HD Graphics 500 | Intel® HD Graphic | SM750 | Intel® HD Graphics 530 | Intel® HD Graphics 520 |
| Carrier Board | PCOM-CA00 (Type 10) | PCOM-CA00 (Type 10) | PCOM-C605 (Type 6) | PCOM-C609 (Type 6) | PCOM-C605 (Type 6) | PCOM-C605 (Type 6) |

PCOM Solution Guide















| PCOM-B639 | PCOM-B641VG | PCOM-B700G | PCOM-B701G | PCOM-C640 | PCOM-C605 | PCOM-C700G |
|---|---|--|--|----------------------------|---------------------------|---|
| COM Express® Basic (125 x 95mm) | COM Express® Compact (95 x 95mm) | COM Express® Basic (125 x 95mm) | COM Express® Basic (125 x 95mm) | NANO-ITX (120 x 120mm) | Mini-ITX (170 x 170mm) | ATX (305 x 244mm) |
| Type 6 | Type 6 | Type 7 | Type 7 | Type 6 | Type 6 | Type 7 |
| * Intel® 6th Generation Core™ * G3902E/ G3900E /i3-6100E/ i3- 6102E/ i5-6442EQ /i5-6440EQ/ i7- 6820EQ/ i7- 6822EQ * Up to 4 CPU cores * 2MB to 8MB cache | * Intel® E3950/ E3940/E3930/ N4200/N3350 * 1.1 GHz to 1.6GHz * 2MB cache | * Intel® Xeon® D1577/D1557/ D1548/D1539/ D1527/D1519/ D1517/D1508/ D1507 * Up to 16 CPU Cores * 12M L2 Cache | * Intel® Atom® Processor C3308/ C3508/C3708/ C3808/C3958 * Up to 16 CPU Cores * 4MB to 16MB Cache | N/A | N/A | N/A |
| SoC | SoC | SoC | SoC | N/A | N/A | N/A |
| * DDR4 2133 MT/s Non-ECC/ECC * Dual Channel | * DDR3L 1866 MT/ s * Non-ECC * Dual Channel | * DDR4 2400 MT/s * 3 SO-DIMM Sockets * Non-ECC/ ECC * Dual Channel | * DDR4 2400 MT/s * 3 SO-DIMM Sockets * Non-ECC/ ECC * Dual Channel | N/A | N/A | N/A |
| 4 x USB 3.0 8 x USB 2.0 | 3x USB 3.0 8x USB 2.0 OTG x 1 port (Optional) | 4x USB 3.0 4x USB 2.0 | 4 x USB2.0 4 x USB3.0 | 2 x USB 3.0 1 x USB 2.0 | 1 x USB2.0 2 x USB3.0 | 4 x USB3.0 |
| 1 x PCle 3.0 x16 8 x PCle 3.0 x1 | 1x PCle 2.0 x4 | 1x PCIe 3.0 x16 10x PCIe 2.0 x1 | 1x PCle 3.0 x8 12x PCle 2.0 x1 | 1x PCle x1 | 1x PCle x1 | 1x PCIe x4 8x PCIe x1 1x PCIe x16 |
| Intel® I219LM | LAN I210-IT | Intel® I210IT 2x KR(10GbE) | Intel® I210IT 4x KR/KX (10GbE) | 2 x GbE | 2 x GbE | 2x GbE 4x 10GbE |
| Intel® High Definition Audio | Intel® High definition Audio | TPM 2.0 (Option) | TPM 2.0 (Option) eMMC (Option) | N/A | N/A | вмс |
| Intel® High Definition Audio | * Intel® HD Graphics 505 * Intel® HD Graphics 500 | N/A | N/A | N/A | N/A | N/A |
| PCOM-C605 (Type 6) | PCOM-C605 (Type 6) | PCOM-C700 (Type 7) | PCOM-C700 (Type 7) | N/A | N/A | PCOM-B700G PCOM-B701G |

Intel® Atom® E3800 series SoC based on Type 10 Mini COM Express® module with DDR3L SDRAM, NANDrive, DDI support, and USB3.0





FEATURES

- Atom® Bay Trail SoC E3800 series processor with industrial support.
- On Board DDR3L DRAM and up to 4GB
- Three PCI Express lanes (optional to Four)
- Support one USB3.0, four USB2.0
- Support NANDrive storage by SATA channel





PCOM-BA00 is a Mini COM Express by 84mm x 55mm with Intel® Bay Trail E3800 series SoC supports PCI Express, dual display, NANDrive storage features.

By low power consumption, wide-temp support, better computing, and cost effective, Portwell promotes with confidence PCOM-BA00 as vertical solution to aim at versatile applications, such as Automation, Military, Networking, Transportation, and so on.

| | | Genera | ıl | | | | | |
|--------------------------------|---|--|----------------------------|--------------|----------|--|--|--|
| Product | | PCOM-BA00 | | | | | | |
| Form Factor | | Type 10, Mini Form Factor COM Express(84 x 55mm) | | | | | | |
| Processor | | Intel® Atom® | | | | | | |
| FIOCESSOI | E3845 | E3827 | E3826 | E3825 | E3815 | | | |
| Core | 4 | 2 | 2 | 2 | 1 | | | |
| Freq. | 1.91 GHz | 1.75 GHz | 1.46 GHz | 1.33 GHz | 1.46 GHz | | | |
| Turbo | N/A | | | | | | | |
| Cache | 2MB | 1MB | 1MB | 1MB | 512KB | | | |
| Processor Graphics | Intel® HD Graphics for Intel Atom® Processor Z3700 Series | | | | | | | |
| Graphics Base Frequency | 542 MHz | 542 MHz | 533 MHz | 533 MHz | 400 MHz | | | |
| Graphics Max Dynamic Frequency | 792 MHz | 792 MHz | 667 MHz | 533 MHz | 400 MHZ | | | |
| HW Encoding | | H.264 and MPEG2 | | | | | | |
| HW Decoding | | H.264, MPEG2, MVC, VC-1, WMV9, JPEG/MJPEG, and VP8 | | | | | | |
| HW Acceleration | | DirectX 11, 0 | OCL 1.2, OGL ES Halti/2.0/ | 1.1, OGL 3.2 | | | | |
| Processor TDP | 10W | 8W | 7 W | 6W | 5W | | | |
| BIOS | | | AMI BIOS | | | | | |
| ECC Memory Supported | | YES | | | | | | |
| Memory | | Supports up | to 4GB DDR3L 1067/1333 N | MT/s SDRAM | | | | |

| | | I/O Interface | | | |
|-------------|--|----------------------|---------------------|--|--|
| SATA | 2x SATA III | | | | |
| USB | 1 x USB 3.0 4 x USB 2.0 | | | | |
| Ethernet | Intel® Ethernet Controller I210IT | | | | |
| | GPIO | | 8 x GPIO | | |
| 0 : 11/0 | I ² C | I ² C Bau | | | |
| Serial I/O | SMBus | E | Baud rate: 100KHz | | |
| | UART | | 2x UART | | |
| PEG | N/A | | | | |
| PCI Express | 3 x PCIe x1 (Optional to 4 x PCIe x1) | | | | |
| | VGA | VGA | 2560 x 1536 @ 24bpp | | |
| Dioploy | LVDS | eDP | 2560 x 1600 @ 24bpp | | |
| Display | HDMI | DP | 2560 x 1600 @ 24bpp | | |
| | пымі | HDMI | 1920 x 1080p@ 24bpp | | |
| Security | | Intel® AES | | | |

MECHANICAL & ENVIRONMENT

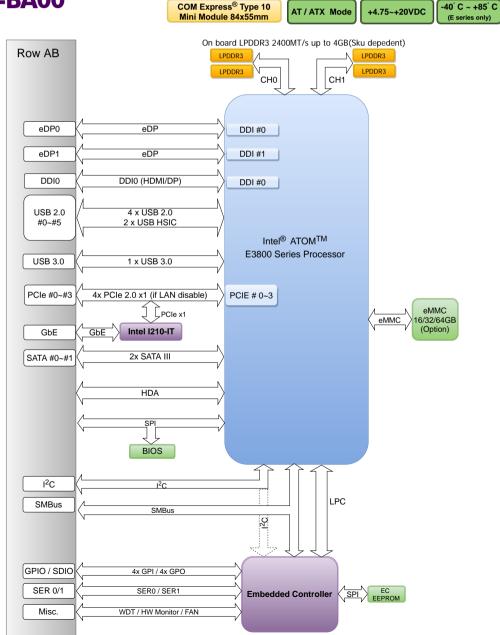
| Dimension | 84 x 55mm |
|--------------------------|---|
| Power DC IN | +4.75VDC ~ +20VDC , AT / ATX mode |
| Storage Temperature | -40°C to 85°C |
| Operation Temperature | -40°C to 85°C |
| Certification | Contact us |
| MTBF | Over 120,000 hours at 40°C |
| Vibration | Random 5Hz to 2KHz, 7.7 grms, 10min in each of 3 axes |
| os | Windows 7/WES7/8/WES8/Embedded Compact7 Linux Fedora/Tizen/Yocto RTOS Windriver |

ORDERING GUIDE

| Product | Ordering P/N | Status |
|---------------------------|--------------|-----------|
| PCOM-BA00-E3805-2G | AB1-3C19 | Available |
| PCOM-BA00-E3815-2G | AB1-3B49 | Available |
| PCOM-BA00-E3825-2G | AB1-3B47 | Available |
| PCOM-BA00-E3827-2G | AB1-3B50 | Available |
| PCOM-BA00-E3845-2G | AB1-3B51 | Available |
| PCOM-BA00-E3845-4G | AB1-3B48 | Available |
| | | |
| Accessory | Ordering P/N | Status |
| PCOM-CA00 (Carrier Board) | AB1-3917 | Available |

BLOCK DIAGRAM

PCOM-BA00



Intel® Atom® E3900 series SoC based on Type 10 Mini COM Express® Rev3.0 module with DDR3L SDRAM, eMMC, DDI support, and USB3.0





FEATURES

- Intel® Atom® E3900 Series ultra low power processor
- 1 DDI, LVDS/eDP display interface
- 4K resolution (*HDMI 3840x2160 @30Hz)
- Support eMMC storage (Option)
- Support -40°C to +85°C wide temperature





PCOM-BA01, a Type 10 COM Express Mini (84mm x 55mm) module based on the 14nm Intel®Atom® processor E3900 product family (6W~12W). The Mini form factor PCOM-BA01 COM Express module supports on board LPDDR4 SDRAM, making it faster than its predecessor.

| General | | | | | |
|--------------------------------|------------------------|-------------------------|----------------------------|-------------------------|------------------------|
| Product | | PCOM-BA01 | | | |
| Form Factor | | СО | M Express Rev3.0 Mini Type | e 10 | |
| Processor | | Intel® Atom® | | Intel® P | entium® |
| Processor | E3950 | E3940 | E3930 | N4200 | N3350 |
| Core | 4 | 4 | 2 | 4 | 2 |
| Freq. | 1.60 GHz | 1.60 GHz | 1.30 GHz | 1.10 GHz | 1.10 GHz |
| Turbo | 2.00 GHz | 1.80 GHz | 1.80 GHz | 2.50 GHz | 2.40 GHz |
| Cache | 2MB | 2MB | 2MB | 2MB | 2MB |
| Processor Graphics | Intel® HD Graphics 505 | Intel® HD Graphics 500 | Intel® HD Graphics 500 | Intel® HD Graphics 505 | Intel® HD Graphics 500 |
| Graphics Base Frequency | 500 MHz | 400 MHz | 400 MHz | 200 MHz | 200 MHz |
| Graphics Max Dynamic Frequency | 650 MHz | 600 MHz | 550 MHz | 750 MHZ | 650 MHZ |
| HW Encoding | | HEVC/H.265 | 5, H.264, MVC, VPS, VP9, J | PEGMJPEG | |
| HW Decoding | | HEVC/H.265, H.264, | MVC, VPS, MPEG2, VC-1, | WMV9, JPEGMJPEG | |
| HW Acceleration | | Gen9LP, DX 9.3/10/11.1/ | 12, OpenGL 4.3, OGLES 3. | 0, OpenCL 1.2, PAVP 2.0 | |
| Processor TDP | 12W | 9.5W | 6.5W | 6W | 6W |
| BIOS | | AMI BIOS | | | |
| ECC Memory Supported | | No | | | |
| Memory | | On Boa | ard LPDDR4 DRAM and up | to 8GB | |

| I/O Interface | | | | | |
|---------------|--|------------------|----------------|---------------------------|--|
| SATA | 2x SATA III | | | | |
| USB | 8 x USB2.0 2 x USB3.0 1 x OTG (Option) | | | | |
| Ethernet | Intel® Ethernet Controller I210IT | | | | |
| | GPIO | | | 8 x GPIO | |
| Carial I/O | | I ² C | | Baud rate: 400KHz | |
| Serial I/O | | SMBus | | Baud rate: 100KHz | |
| | UART | | | 2x UART | |
| PEG | N/A | | | | |
| PCI Express | | | 1x PClex4 o | r 4x PCIe x1 | |
| | LVDS eDP | | | 1920x1600@60Hz | |
| Display HDMI | DP | | 4096x2160@60Hz | | |
| | нимі | HDMI | | 3840x2160@30Hz (Optional) | |
| Security | | | Intel® | AES | |

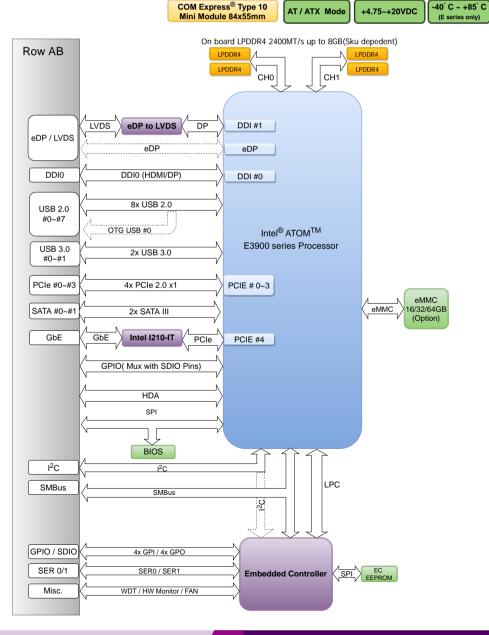
MECHANICAL & ENVIRONMENT

| Dimension | 84 x 55mm |
|--------------------------|--|
| Power DC IN | +4.75VDC ~ +20VDC , AT / ATX mode |
| Storage Temperature | −40°C to 85°C |
| Operation Temperature | −40°C to 85°C |
| Certification | Contact us |
| MTBF | Over 120,000 hours at room ambient 40° C |
| Vibration | Random 5Hz to 2KHz, 7.7 grms, 10min in each of 3 axes |
| os | Win 7/8, WES 7/8 Linux Tizen/Fedora/Yocto RTOS Windriver |

BLOCK DIAGRAM

PCOM-BA01

ORDERING GUIDE Status Product Ordering P/N AB1-3G73 Available PCOM-BA01-E3950-4G PCOM-BA01-E3940-4G AB1-3G74 Available PCOM-BA01-E3930-4G Contact us Available PCOM-BA01-N4200-4G Contact us Available PCOM-BA01-N3350-4G Contact us Available PCOM-BA01-E3950-8G Contact us Available PCOM-BA01-E3940-8G Contact us Available AB1-3G27 PCOM-BA01-E3930-8G Available PCOM-BA01-N4200-8G Contact us Available PCOM-BA01-N3350-8G Contact us Available Ordering P/N Status Accessory PCOM-CA00 AB1-3917 Available (uATX ATX Carrier Board)



PCOM-B632VG

Intel® Atom® E3800 series SoC based on Type 6 COM Express® module with DDR3L SO-DIMM sockets, VGA, eDP, DDI, GbE, and SATA 3 Gb/s





FEATURES

- Atom® Bay Trail SoC E3800 series processor with industrial support
- Supports up to four PCI Express lanes, four x 1 lanes can be configured to one x 4 lane
- Supports one DDR3L 1067MT/s SDRAM, UP to 8GB
- Supports one USB3.0 port





PCOM-B632VG is designed to offer good EMC protection by latest mobile platform, SoC(System-On-Chip) integrated remote technology and embedded controller. Also PCOM-B632VG provides high performance for various display, eDP and HDMI.

The PCOM-B632VG COM Express® module has been enhanced by Portwell in response to market demand for an even lower power platform to take advantage of the Intel® Atom® processor's already compact design. In fact, since its initial inception, Portwell's expanding Intel Atom processorbased COM Express product portfolio has now grown to include industrial temperature range support. Portwell's versatile COM Express modules adapt to these changes by enabling designers to partition commodity hostprocessors from proprietary baseboards, thereby minimizing current and future design risks during the initial phase of development.

| General | | | | | | | |
|--------------------------------|---|---------------|----------------------------|----------------|----------|--|--|
| Product | PCOM-B632VG | | | | | | |
| Form Factor | | Type 6, Compa | act Form Factor Com Expres | ss (95 x 95mm) | | | |
| Processor | Intel® Atom® | | | | | | |
| 1 10003301 | E3845 | E3827 | E3826 | E3825 | E3815 | | |
| Core | 4 | 2 | 2 | 2 | 1 | | |
| Freq. | 1.91 GHz | 1.75 GHz | 1.46 GHz | 1.33 GHz | 1.46 GHz | | |
| Turbo | | | N/A | | | | |
| Cache | 2MB 1MB 1MB 1MB 512KB | | | | | | |
| Processor Graphics | Intel® HD Graphics for Intel Atom® Processor Z3700 Series | | | | | | |
| Graphics Base Frequency | 542 MHz 542 MHz 533 MHz 533 MHz 4 | | | | 400 MHz | | |
| Graphics Max Dynamic Frequency | 792 MHz 792 MHz 667 MHz 533 MHz 400 MHZ | | | | | | |
| HW Encoding | H.264 and MPEG2 | | | | | | |
| HW Decoding | H.264, MPEG2, MVC, VC-1, WMV9, JPEG/MJPEG, and VP8 | | | | | | |
| HW Acceleration | DirectX 11, OCL 1.2, OGL ES Halti/2.0/1.1, OGL 3.2 | | | | | | |
| Processor TDP | 10W 8W 7W 6W 5W | | | | | | |
| BIOS | Phoenix UEFI BIOS | | | | | | |
| ECC Memory Supported | | | No | | | | |
| Memory | Supports up to 8GB DDR3L 1066/1333 MT/s SDRAM | | | | | | |

| | | I/O Interface | | | | |
|-------------|---------------------------|--|---------------------|--|--|--|
| SATA | 2x SATA II | | | | | |
| USB | 4 x USB 2.0 1 x USB3.0 | | | | | |
| Ethernet | | Intel® Ethernet Controller I210IT | | | | |
| | GPIO | | 8 x GPIO | | | |
| Serial I/O | I2C | | Baud rate: 400KHz | | | |
| Serial I/O | SMBus | | Baud rate: 100KHz | | | |
| | UART | | 2x UART | | | |
| PEG | N/A | | | | | |
| PCI Express | | 3x PCle x1 Gen2 (Optional to 4x PCle x1) | | | | |
| | VGA | VGA | 2560 x 1536 @ 24bpp | | | |
| Display | LVDS | eDP | 2560 x 1600 @ 24bpp | | | |
| Display | HDMI | DP | 2560 x 1600 @ 24bpp | | | |
| | поімі | HDMI | 1920 x 1080p@ 24bpp | | | |
| Security | | Intel® AES | | | | |

PCOM-B632VG

MECHANICAL & ENVIRONMENT

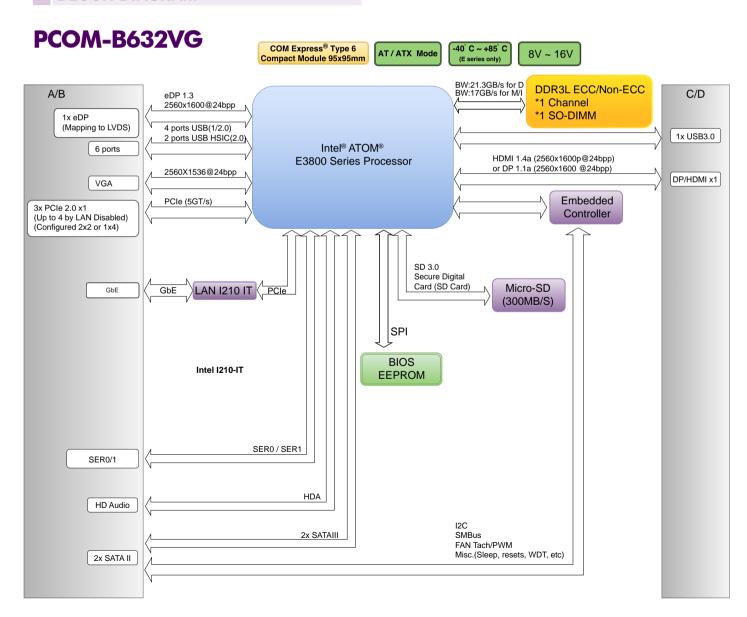
| Dimension | 95mm x 95mm | | | | | |
|--------------------------|---|--|--|--|--|--|
| Power DC IN | +8VDC ~ +16VDC | | | | | |
| Storage Temperature | −40°C to 85°C | | | | | |
| Operation Temperature | -40°C to 85°C | | | | | |
| Certification | Contact us | | | | | |
| MTBF | Over 120,000 hours at room ambient 40°C | | | | | |
| Vibration | Random 5Hz to 2KHz, 7.7 grms, 10min in each of 3 axes | | | | | |
| os | Windows 7(32/64)/win10(64) Linux Wind River/Yocto RTOS Windriver Android | | | | | |

ORDERING GUIDE

| Product | Ordering P/N | Status |
|--------------------|--------------|-----------|
| PCOM-B632VG-E3845- | AB1-3A36 | Available |
| PCOM-B632VG-E3827 | AB1-3A33 | Available |
| PCOM-B632VG-E3826 | AB1-3A34 | Available |
| PCOM-B632VG-E3825- | AB1-3A35 | Available |
| PCOM-B632VG-E3815 | AB1-3A40 | Available |

| Accessory | Ordering P/N | Status |
|---------------------------------------|--------------|-----------|
| Heat Sink | B8308040 | Available |
| Heat Spreader | B8307650 | Available |
| PCOM-C605 (MINI-ITX Carrier Board) | AB1-3998 | Available |
| PCOM-C640 (NANO-ITX Carrier Board) | AB1-3D18Z | Available |
| PCOM-C600 (uATX ATX Carrier Board) | AB1-3761Z | Available |

BLOCK DIAGRAM



PCOM-B634VG

Intel® Pentium® / Xeon® D-1500 series Processor based on Type 6 COM Express® 2.0 module with DDR4 ECC/Non-ECC 3x SO-DIMM sockets, VGA, DDI, PCIex 16, 10GbE, USB 3.0, and SATA 6 Gb/s





FEATURES

- Intel® Pentium® / Xeon® D-1500 series Processor 14nm process (Broadwell-DE)
- Support DDR4-2133/2400 SDRAM on Three SO-DIMM Sockets, up to 48GB
- One VGA, One HDMI, and Two 10GbE Interfaces
- 7x USB 2.0, 4x USB 3.0, 4x SATA III,
 8x PCle x1 Gen 2.0, and 1x PCle x16 Gen 3.0





Portwell PCOM-B634VG is designed with Intel® new Xeon processor with 8 CPU cores, 10GbE Ethernet KR interface and DDR4 ECC/Non-ECC SO-Dimm support which provide high CPU computing, excellent Ethernet performance. Extend PCIE Gen3 ports in PCOM-B634 can support high speed IO card for more application. With VGA and legacy interface support, customer can upgrate system easy and fast.

| | General | | | | | | |
|--------------------------------|---|--------------|-----------------------|------------------------|----------|----------|--|
| Product | | PCOM-B634 | | | | | |
| Form Factor | | Type 6 | 6, Compact Form Facto | r Com Express (125 x s | 95mm) | | |
| Processor | | Intel® Xeon® | | Intel® Pentium® | | | |
| 110063301 | D1577 | D1548 | D1527 | D1519 | D1517 | D1508 | |
| Core | 16 | 8 | 4 | 4 | 4 | 2 | |
| Freq. | 1.30 GHz | 2.00 GHz | 2.20 GHz | 1.50 GHz | 1.60 GHz | 2.20 GHz | |
| Turbo | 2.10 GHz | 2.60 GHz | 2.70 GHz | 2.10 GHz | 2.20 GHz | 2.60 GHz | |
| Cache | 24 MB | 12 MB | 6 MB | 6 MB | 6 MB | 3 MB | |
| Processor Graphics | | SM750 | | | | | |
| Graphics Base Frequency | | | | | | | |
| Graphics Max Dynamic Frequency | | | | | | | |
| HW Encoding | N/A | | | | | | |
| HW Decoding | | | | | | | |
| HW Acceleration | | | | | | | |
| Processor TDP | 45 W | 45 W | 35 W | 25 W | 25 W | 25 W | |
| BIOS | AMI UEFI BIOS | | | | | | |
| ECC Memory Supported | Yes | | | | | | |
| Memory | Supports up to 48GB DDR4 2133/2400 MT/s SDRAM | | | | | | |

| | I/O Interface | | | | | |
|-------------|---|------------------------------|--|--|--|--|
| SATA | 4x S/ | ATA III | | | | |
| USB | 4 x USB2.0 4 x USB3.0 | | | | | |
| Ethernet | Intel® Ethernet Controller I210 | LM for 1GbE. 2x KR for 10GbE | | | | |
| | GPIO 8 GPIO (4 GPI and 4 GPO) | | | | | |
| Serial I/O | I ² C | Baud Rate : 400KHz | | | | |
| Geriai i/O | SMBus | Baud Rate : 100KHz | | | | |
| | UART | 2 Serial Port (TX and RX) | | | | |
| PEG | N/A | | | | | |
| PCI Express | 1x PCIe 3.0 x16 8x PCIe 2.0 x1 | | | | | |
| Display | VGA: 1920x1440@24bpp | | | | | |
| Security | TPM 2.0 (Infineon SLB9665) , Intel® AES | | | | | |

PCOM-B634VG

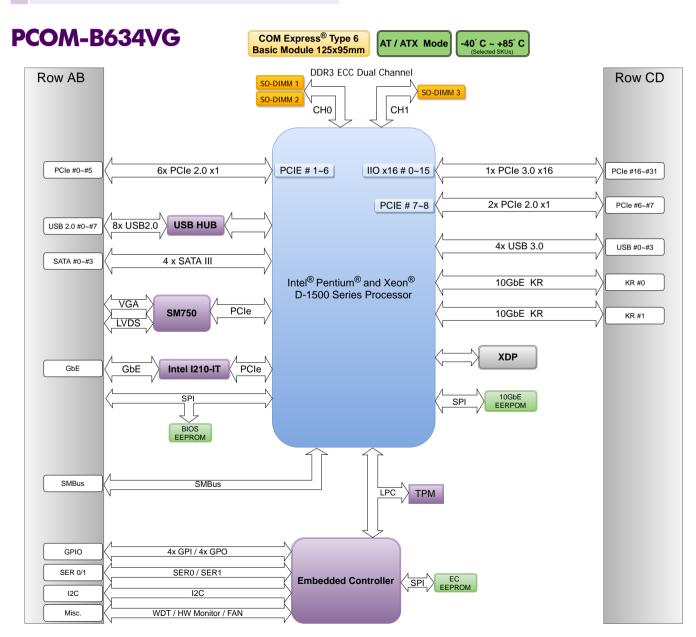
MECHANICAL & ENVIRONMENT

| Dimension | 125x95mm | | | | | |
|--------------------------|---|--|--|--|--|--|
| Power DC IN | +12VDC | | | | | |
| Storage Temperature | -40°C~+85°C | | | | | |
| Operation Temperature | -40°C~+85°C | | | | | |
| Certification | Contact us | | | | | |
| MTBF | Over 100,000 hours at 40°Cat both 35° C and 55° C | | | | | |
| Vibration | Random 5Hz to 2KHz, 7.7 grms, 10min in each of 3 axes | | | | | |
| os | Windows 64 bit OS support RHEL/SUSE/Fedora/Ubuntu/CentOS/Xen & KVM/Yocto/ FreeBSD | | | | | |

ORDERING GUIDE

| Product | Ordering P/N | Status | |
|---------------------------------------|--------------|-----------|--|
| PCOM-B634VG-D-1577 | AB1-3D94 | Available | |
| PCOM-B634VG-D-1548 | AB1-3D95 | Available | |
| PCOM-B634VG-D-1527 | AB1-3D96 | Available | |
| PCOM-B634VG-D-1519 | AB1-3D97 | Available | |
| PCOM-B634VG-D-1517 | AB1-3D98 | Available | |
| PCOM-B634VG-D-1508 | AB1-3D99 | Available | |
| Accessory | Ordering P/N | Status | |
| PCOM-B634VG Cooler | B9971410 | Available | |
| PCOM-C609 (uATX ATX Carrier Board) | AB1-3D19 | Available | |

BLOCK DIAGRAM



PCOM-B637VG

Intel® 6th Generation Core™ Kaby Lake-S / Skylake-S processors based on Type VI Compact-COM Express 2.0 module with DDR4 SDRAM on Two SO-DIMM slots, VGA, eDP, DP, Gigabit Ethernet, PCIE, SATA and USB





FEATURES

- Intel® 6th GEN Core™ Processors Support (Kaby Lake-S / Skylake-S 35W)
- Support 2x DDR4-2133 ECC/Non-ECC SO-DIMMs, up to 32GB
- Support USB 2.0/3.0, SATA III, 7x PCle 3.0 x1 and 1x PCle 3.0 x16
- One VGA, three Displayport
- Wide voltage support, from 6V to 18V





PCOM-B637VG is Portwell's first module with desktop CPU. It provides customers four important factors, high performance with affordable cost, DDR 4 memory support, Gen 3 PCIe support, and 30% faster graphic performance. The desktop CPU on module is a new idea which offers customer higher computing power but lower cost comparing to mobile solutions. The DDR4 support is also another important point for higher performance. PCOM-B637VG can support both ECC and Non-ECC DDR4 by different PCH SKUs. This is good for different applications. The Gen 3 PCIe support provides faster PCIe speed so that the performance of PCIe devices will be better. It is crucial for Networking and Medical related applications. PCOM-B637VG provides one PCIex16, eight PCIex1 (Option to one PCIex4), four USB 3.0, and four SATA3.

| | General | | | | | | | | |
|--------------------------------|---|--|------------------------------|------------------------------|------------------------------|------------------------------|------------------------------|------------------------------|------------------------------|
| Product | | PCOM-B637VG | | | | | | | |
| Form Factor | | Type 6, Compact Form Factor Com Express (125 x 95mm) | | | | | | | |
| Processor | | Intel® Pentium® Intel® Core™ | | | | | | | |
| 1 10000001 | G4400T | G4500T | i3-6100T | i3-6300T | i5-6600T | i5-6500T | i5-6400T | i7-6700T | i7-6700TE |
| Core | 2 | 2 | 2 | 2 | 4 | 4 | 4 | 4 | 4 |
| Freq. | 2.90 GHz | 3.00 GHz | 3.20 GHz | 3.30 GHz | 2.70 GHz | 2.50 GHz | 2.20 GHz | 2.80 GHz | 2.40 GHz |
| Turbo | NA | NA | NA | NA | 3.50 GHz | 3.10 GHz | 2.80 GHz | 3.60 GHz | 3.40 GHz |
| Cache | 3МВ | 3МВ | 3МВ | 4MB | 6MB | 6MB | 6MB | 8MB | 8MB |
| Processor Graphics | Intel® HD Graphics 510 | Intel® HD Graphics 530 | Intel® HD Graphics 530 | Intel® HD Graphics 530 | Intel® HD Graphics 530 | Intel® HD Graphics 530 | Intel® HD Graphics 530 | Intel® HD Graphics 530 | Intel® HD Graphics 530 |
| Graphics Base Frequency | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz |
| Graphics Max Dynamic Frequency | 950 MHz | 950 MHz | 950 MHz | 950 MHz | 1.1 GHz | 1.1 GHz | 950 MHz | 1.1 GHz | 1.0 GHz |
| HW Encoding | | | | | | | | | |
| HW Decoding | | | | | N/A | | | | |
| HW Acceleration | | | | | | | | | |
| Processor TDP | 35W | 35W | 35W | 35W | 35W | 35W | 35W | 35W | 35W |
| BIOS | AMI BIOS | | | | | | | | |
| ECC Memory Supported | Depend on chipset. H110 (Non-ECC), Q170 (Non-ECC), C236 (ECC) | | | | | | | | |
| Memory | | 2 SODIMM DDR4 ECC / Non-ECC up to 32GB 2133MHz | | | | | | | |

| | | I/O Interface | | | | |
|-------------|---|---------------|--------------------|--|--|--|
| SATA | | 4x SATA III | | | | |
| USB | 4 x USB 3.0 8 x USB 2.0 | | | | | |
| Ethernet | | Intel® I219LM | | | | |
| | GPIO | | 8 GPIO | | | |
| Serial I/O | I ² C | | Baud Rate : 400KHz | | | |
| Octiai i/O | SMBus | | Baud Rate : 100KHz | | | |
| | UART | | 2x UART | | | |
| PEG | 1x PCles x16 Gen3 | | | | | |
| PCI Express | 8x PCle Gen2, can be configured to x1,x2,x4 | | | | | |
| | VGA VGA 1920 x 1200 @ 60Hz | | | | | |
| Display | LVDS | LVDS | 4096x2304@60Hz | | | |
| ызры | HDMI | DP | 4096x2304@60Hz | | | |
| | 1 101011 | HDMI | 4096x2304@24Hz | | | |
| Security | | TPM | | | | |

PCOM-B637VG

MECHANICAL & ENVIRONMENT

| Dimension | 125 x 95mm |
|--------------------------|---|
| Power DC IN | Normal: +12V DC Wide range: + 8 VDC ~ + 18 VDC AT/ ATX Mode |
| Storage Temperature | 0°C to 60°C |
| Operation Temperature | 0°C to 60°C |
| Certification | Contact us |
| MTBF | Over 100,000 hours at both 35° C and 55° C |
| Vibration | Random 5Hz to 2KHz, 7.7 grms, 10min in each of 3 axes |
| OS | Windows 7/ 8/ 8.1/ 10/ Microsoft Windows 2008 R2 SP1/ 2012/ 2012 R2 Linux Fedora 22/ Ubuntu 15.04 |

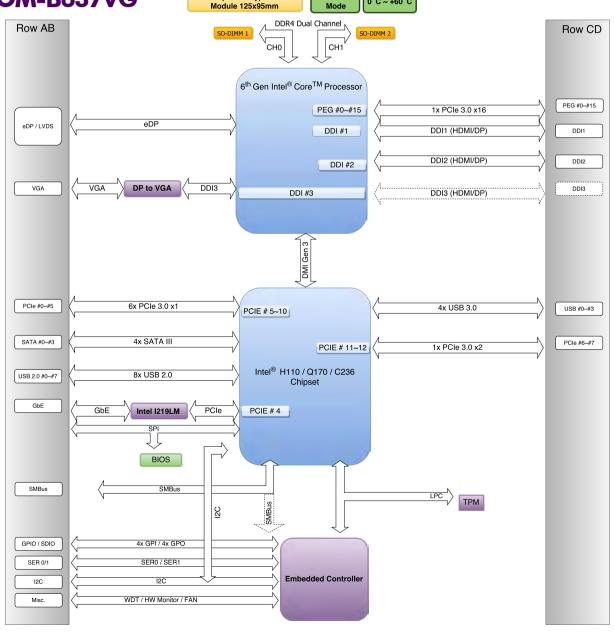
ORDERING GUIDE

| Product | Ordering P/N | Status |
|------------------|--------------|-----------|
| PCOM-B637VG-Q170 | AB1-3E37 | Available |
| PCOM-B637VG-H110 | AB1-3E34 | Available |
| PCOM-B637VG-C236 | AB1-3E36 | Available |

| Accessory | Ordering P/N | Status | |
|-------------------------|--------------|-----------|--|
| PCOM-C605 carrier board | AB1-3998 | Available | |
| PCOM-B637VG Cooler | B9971421 | Available | |
| PCOM-B637VG Heat Sink | B8308650 | Available | |

BLOCK DIAGRAM

PCOM-B637VG COM Express® Type 6 Basic Module 125x95mm AT / ATX Mode O' C ~ +60' C



PCOM-B638VG

Intel® Kaby Lake-U/Skylake-U Core™ i7/i5/i3 processor based on Type VI Compact-COM Express 2.0 module with DDR4 SDRAM on SO-DIMM slots, VGA, LVDS, Display-port, Gigabit Ethernet, PCIE, SATA, USB, and OTG





FEATURES

- Kaby Lake-U / Skylake-U is the 7th / 6th Generation Intel[®] CoreTM Processor with 14nm and brand new architecture provide more performance
- Support DDR4-2133 MT/S Non-ECC SDRAM on one SO-DIMM slots, up to 16 GB
- Two SO-DIMM slots, up to 32GB
- One VGA, two DDI(one default optional) and LVDS
- Wide voltage support, from 6V to 18V





PCOM-B638VG brings three important factors, DDR4 memory support, Gen3 PCIe support, and 30% faster graphic performance. The Gen3 PCIe support provides faster PCIe speed so that the performance of PCIe expansion card will be better. It is crucial for Networking and Medical related applications. The enhanced graphic performance brings 4K support. The OTG support gives customer more flexibilities on developing new applications in different usages.

| General | | | | | | | | |
|--------------------------------|---|------------------------|------------------------|------------------------|--|--|--|--|
| Product | PCOM-B638VG | | | | | | | |
| Form Factor | Type 6, Compact Form Factor Com Express (95 x 95mm) | | | | | | | |
| Processor | Intel® Celeron® | | Intel® Core™ | | | | | |
| Tiocessor | 3955U | i3-6100U | i5-6300U | i7-6600U | | | | |
| Core | 2 | 2 | 2 | 2 | | | | |
| Freq. | 2.00 GHz | 2.30 GHz | 2.40 GHz | 2.60 GHz | | | | |
| Turbo | NA | NA 3.00 GHz | | | | | | |
| Cache | 2MB | 2MB 3MB 3MB | | | | | | |
| Processor Graphics | Intel® HD Graphics 510f | Intel® HD Graphics 520 | Intel® HD Graphics 520 | Intel® HD Graphics 520 | | | | |
| Graphics Base Frequency | 300 MHz | 300 MHz | 300 MHz | 300 MHz | | | | |
| Graphics Max Dynamic Frequency | 900 MHz | 1.00 GHz | 1.00 GHz | 1.05 GHz | | | | |
| HW Encoding | | | | | | | | |
| HW Decoding | | N | /A | | | | | |
| HW Acceleration | | | | | | | | |
| Processor TDP | 15W | 15W 15W 15W | | | | | | |
| BIOS | AMI BIOS | | | | | | | |
| ECC Memory Supported | NO | | | | | | | |
| Memory | 2 SODIMM DDR4 up to 32GB 2133MHz | | | | | | | |

| I/O Interface | | | | | | |
|---------------|---|------------------|---------------------------|--|--|--|
| SATA | 2 x SATA III (Port 0/1) 1 x SATA III (Port 2) (Optional) | | | | | |
| USB | 8 x USB2.0 (Port 0~7) USB OTG (Optional) (Port 7) 4 x USB3.0 (Port 0/1/2/3) | | | | | |
| Ethernet | | Intel® I219LM | | | | |
| | GPIO | | 8 GPIO | | | |
| Serial I/O | I ² C | | Baud Rate : 400KHz | | | |
| Condi i/C | SMBus | | Baud Rate : 100KHz | | | |
| | UART | | 2x UART | | | |
| PEG | | 1x PCles x4 Gen3 | | | | |
| PCI Express | 1x PCIe x4 Gen2 1x PCIe x1 Gen2 | | | | | |
| | VGA | VGA | 1920x1200@60 Hz | | | |
| Display | LVDS | LVDS | 1920x1600@60Hz | | | |
| Display | HDMI | DP | 4096x2160@60Hz | | | |
| | HOWII | HDMI | 3840x2160@30Hz (Optional) | | | |
| Security | | TPM | | | | |

PCOM-B638VG

MECHANICAL & ENVIRONMENT

| Dimension | 95 x 95mm |
|--------------------------|---|
| Power DC IN | Normal: +12V DC Wide range: + 8 VDC ~ + 18 VDC AT/ ATX mode |
| Storage Temperature | 0°C to 60°C |
| Operation Temperature | 0°C to 60°C |
| Certification | Contact us |
| MTBF | Over 100,000 hours at both 40° C |
| Vibration | Random 5Hz to 2KHz, 7.7 grms, 10min in each of 3 axes |
| os | Windows 7/ 8/ 8.1/ 10/ Microsoft Windows 2008 R2 SP1/ 2012/ 2012 R2 Linux Fedora 22/ Ubuntu 15.04 |

BLOCK DIAGRAM

ORDERING GUIDE

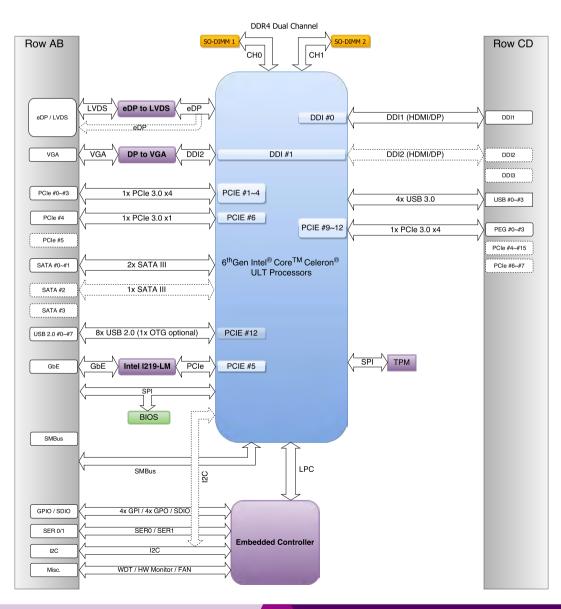
| Product | Ordering P/N | Status |
|-------------------------|--------------|-----------|
| PCOM-B638VG-6600U | AB1-3E39 | Available |
| PCOM-B638VG-6300U | AB1-3E38 | Available |
| PCOM-B638VG-6100U | AB1-3E32 | Available |
| PCOM-B638VG-3955U | AB1-3E77 | Available |
| PCOM-B638VG-7600U | AB1-3G88 | Available |
| PCOM-B638VG-7300U | AB1-3G87 | Available |
| PCOM-B638VG-7100U | AB1-3G86 | Available |
| PCOM-B638VG-3965U | AB1-3G85 | Available |
| Accessory | Ordering P/N | Status |
| PQ7-C605 carrier board | AB1-3998 | Available |
| PCOM-B638VG Cooler | B9971380 | Available |
| PCOM-B638VG Heat Sink | B8308660 | Available |
| PCOM-B638 Heat Spreader | B8308500 | Available |

PCOM-B638VG

COM Express® Type 6
Compact Module 95x95mm

AT / ATX Mode

0° C ~ +60° C



PCOM-B639VG

Intel® Core[™] Kaby Lake-H/Skylake-H Processor based on Type VI COM Express module with DDR4 SDRAM, VGA, LVDS, Gigabit Ethernet, SATA 3.0 and USB





FEATURES

- Kaby Lake-H / Skylake-H is the 7th / 6th Generation Intel[®] CoreTM Processor with 14nm and brand new architecture provide more performance
- Support DDR4-2133 MT/S ECC/Non-ECC SDRAM on two SO-DIMM slots, up to 16 GB
- Support faster I/O interfaces on 8x PCle Gen3 lanes (four x 1 can be configured to on x4 lane)
- One VGA, three DDI(one default optional)
- and one embedded display port Wide voltage support, from 6V to 18V





PCOM-B639VG brings three important factors, DDR 4 memory support, Gen 3 PCIe support, and 30% faster graphic performance. The DDR4 is trend and it supports both ECC and Non-ECC with the same pin definition. In other words, customer can use both ECC and Non-ECC memories depending their application and demand. In order to achieve that, all the PCH SKUs are considered in development stage to make sure that customer has various models to meet different requirements in cost, performance, and memory type. The Gen 3 PCIe support provides faster PCIe speed so that the performance of PCIe expansion card will be better. It is crucial for Networking and Medical related applications. The enhanced graphic performance brings 4K support.

| | General | | | | | | | | | | | | |
|-----------------------------------|------------------------------|--|------------------------------|------------------------------|------------------------------|------------------------------|------------------------------|------------------------------|------------------------------|------------------------------|------------------------------|------------------------------|------------------------------|
| Product | | PCOM-B639VG | | | | | | | | | | | |
| Form Factor | | Type 6, Compact Form Factor Com Express (125 x 95mm) | | | | | | | | | | | |
| | Intel® C | eleron® | | | | | | Intel® Core™ | l | | | | |
| Processor | G3902E | G3900E | i3-6100E | i3-6102E | i5- 6442EQ | i5- 6440EQ | i7- 6820EQ | i7- 6822EQ | 7100E | 7102E | 7440EQ | 7442EQ | 7820EQ |
| Core | 2 | 2 | 2 | 2 | 4 | 4 | 4 | 4 | 2 | 2 | 4 | 4 | 4 |
| Freq. | 1.60 GHz | 2.40 GHz | 2.70 GHz | 1.90 GHz | 1.90 GHz | 2.70 GHz | 2.80 GHz | 2.00 GHz | 2.90 GHz | 2.10 GHz | 2.90 GHz | 2.10 GHz | 3.00 GHz |
| Turbo | NA | NA | NA | NA | 2.70 GHz | 3.40 GHz | 3.50 GHz | 2.80 GHz | NA | NA | 3.60 GHz | 2.90 GHz | 3.70 GHz |
| Cache | 2MB | 2MB | 3MB | 3MB | 6MB | 6MB | 8MB | 8MB | 3МВ | 3MB | 6MB | 6MB | 8MB |
| Processor Graphics | Intel® HD Graphics 510 | Intel® HD Graphics 510 | Intel® HD Graphics 530 | Intel® HD Graphics 630 |
| Graphics Base Frequency | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz | 350 MHz |
| Graphics Max Dynamic Frequency | 950 MHz | 950 MHz | 950 MHz | 950 MHz | 1.00 GHz | 1.00 GHz | 1.00 GHz | 1.00 GHz | 950 MHz | 950 MHz | 1.00 GHz | 1.00 GHz | 1.00 GHz |
| HW Encoding | | | | | | | | | | | | | |
| HW Decoding | | | | | | | N/A | | | | | | |
| HW Acceleration | | | | | | | | | | | | | |
| Processor TDP | 25W | 35W | 35W | 25W | 25W | 45W | 45W | 25W | 35W | 25W | 45W | 25W | 45W |
| BIOS | | | | | | | AMI BIOS | | | | | | |
| ECC Memory Supported | YES | YES | YES | YES | NO | NO | NO | NO | YES | YES | NO | NO | NO |
| Memory | | | | | 2 SODIM | M DDR4 EC | C / Non-ECC | up to 32GB | 2133MHz | | | | |

| I/O Interface | | | | | | | |
|---------------|-------------------|--------------------------|--------------------|--|--|--|--|
| SATA | | 4 x SATA III | | | | | |
| USB | | 8 x USB2.0 4 x USB3.0 | | | | | |
| Ethernet | | Intel® I219LM | | | | | |
| | GPIO | | 8 GPIO | | | | |
| Serial I/O | I ² C | | Baud Rate : 400KHz | | | | |
| Serial I/O | SMBus | | Baud Rate : 100KHz | | | | |
| | UART | | 2x UART | | | | |
| PEG | 1x PCles x16 Gen3 | | | | | | |
| PCI Express | | 8 x PCle x1 Gen3 | | | | | |
| | VGA | VGA | 1920 x 1200@60Hz | | | | |
| Diaploy | LVDS | LVDS | 1920 x 1200@60Hz | | | | |
| Display | LIDAM | DP | 3840x2160@60Hz | | | | |
| | HDMI | HDMI | 3840x2160@60Hz | | | | |
| Security | TPM | | | | | | |

PCOM-B639VG

MECHANICAL & ENVIRONMENT

| Dimension | 125 x 95mm |
|--------------------------|---|
| Power DC IN | Normal: +12V DC Wide range: + 8 VDC ~ + 18 VDC AT/ ATX mode |
| Storage Temperature | 0°C to 60°C |
| Operation Temperature | 0°C to 60°C |
| Certification | Contact us |
| MTBF | Over 100,000 hours at both 40° C |
| Vibration | Random 5Hz to 2KHz, 7.7 grms, 10min in each of 3 axes |
| os | Windows 7/ 8/ 8.1/ 10/ Microsoft Windows 2008 R2 SP1/ 2012/ 2012 R2 Linux Fedora 22/ Ubuntu 15.04 |
| | |

| Accessory | Ordering P/N | Status |
|------------------------|--------------|-----------|
| PQ7-C605 carrier board | AB1-3998 | Available |
| Cooler | B9971391 | Available |
| Heat Sink | B8308670 | Available |
| Heat Spreader | B8308510 | Available |

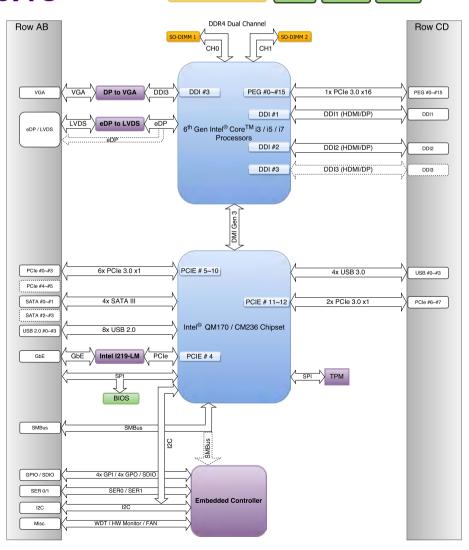
ORDERING GUIDE

| Product | Ordering P/N | Status |
|--------------------|--------------|-----------|
| PCOM-B639VG-6822EQ | AB1-3E06 | Available |
| PCOM-B639VG-6820EQ | AB1-3E31 | Available |
| PCOM-B639VG-6442EQ | AB1-3E28 | Available |
| PCOM-B639VG-6440EQ | AB1-3E29 | Available |
| PCOM-B639VG-6102EQ | AB1-3E26 | Available |
| PCOM-B639VG-6100EQ | AB1-3E27 | Available |
| PCOM-B639VG-G3902E | AB1-3E35 | Available |
| PCOM-B639VG-G3902E | AB1-3E25 | Available |
| PCOM-B639VG-G3900E | AB1-3G48 | Available |
| PCOM-B639VG-7820EQ | AB1-3G46 | Available |
| PCOM-B639VG-7442EQ | AB1-3G47 | Available |
| PCOM-B639VG-7440EQ | AB1-3G44 | Available |
| PCOM-B639VG-7102E | AB1-3G45 | Available |
| PCOM-B639VG-7100EZ | AB1-3E38 | Available |

BLOCK DIAGRAM

PCOM-B639VG





PCOM-B641VG Intel® Atom® E3900 series SoC based on Type 6 COM Express® Rev3.0 module with DDR3L 2x SO-DIMM sockets, VGA, eDP/LVDS, DDI, GbE, and SATA 6 Gb/s





FEATURES

- Intel® Atom® E3900 Series ultra low power processor
- Support DDR3L-1866 MT/s SDRAM on two SO-DIMM sockets
- 8x USB 2.0 or 4x USB2.0 + 4x USB 3.0
- Wide voltage support, from 8V to 18V





PCOM-B641VG, COM Express® Type 6 Compact Module designed with 6th Generation Intel® ATOM® processors, supporting wide operation temperature -40°C to +85°C (on E series processors only).

| | General | | | | | | | |
|--------------------------------|---|----------------------------|-----------------------------|---------------------------|------------------------|--|--|--|
| Product | PCOM-B641VG | | | | | | | |
| Form Factor | COM Express®Type 6 Compact Rev. 3.0 | | | | | | | |
| Processor | Intel® Celeron® | Intel® Pentium® | Intel® ATOM® | Intel® ATOM® | Intel® ATOM® | | | |
| Processor | N3350 | N4200 | E3930 | E3940 | E3950 | | | |
| Core | 2 | 4 | 2 | 4 | 4 | | | |
| Freq. | 1.10 GHz | 1.10 GHz | 1.30 GHz | 1.60 GHz | 1.60 GHz | | | |
| Turbo | 2.40 GHz | 2.50 GHz | 1.80 GHz | 1.80 GHz | 2.00 GHz | | | |
| Cache | 2 MB | 2 MB 2 MB 2 MB 2 MB | | | | | | |
| Processor Graphics | Intel® HD Graphics 500 | Intel® HD Graphics 505 | Intel® HD Graphics 500 | Intel® HD Graphics 500 | Intel® HD Graphics 505 | | | |
| Graphics Base Frequency | 200.00 MHz | 200.00 MHz | 400.00 MHz | 400.00 MHz | 500.00 MHz | | | |
| Graphics Max Dynamic Frequency | 650.00 MHz | 750.00 MHz | 550.00 MHz | 600.00 MHz | 650.00 MHz | | | |
| HW Encoding | | HEVC/H.265 | i, H.264, MVC, VP8, VP9, JI | PEG/MJPEG | | | | |
| HW Decoding | | HEVC/H.265, H.264, MV | C, VP8, VP9, MPEG2, VC- | 1, WMV9, JPEG/MJPEG | | | | |
| HW Acceleration | Gen9 | LP, DX 9.3/10/11.1/12, Ope | enGL 4.3, OGL ES 3.0, Oper | nCL 1.2, PAVP 2.0, HDCP 1 | 1.4/2.0 | | | |
| Processor TDP | 6 W | 6 W | 6.5W | 9.5W | 12W | | | |
| BIOS | AMI Aptio5 UEFI BIOS | | | | | | | |
| ECC Memory Supported | | | No | | | | | |
| Memory | 2x DDR3L SO-DIMM sockets Dual channel Up to 1866 MT/s | | | | | | | |

| | | I/O Interface | |
|-------------|---|---|-----------------------------|
| SATA | | 2x SATA III | |
| USB | | 8x USB 2.0 / 1 OTG (optional) or 4x USB 2.0 + 3x USB 3.0 | |
| Ethernet | 1 GbE (I210-IT) | | |
| | GPIO | | 8 GPIO (4 GPI and 4 GPO) |
| Serial I/O | I ² C SMBus | | Baud Rate : 400KHz |
| Serial I/O | | | Baud Rate : 100KHz |
| | UART | | 2 Serial Port (TX and RX) |
| PEG | N/A | | |
| PCI Express | | 1x PCIe 2.0 x4 (1x4 / 2x2 / 4x1) | |
| | Default | Options | Resolution |
| | VOA. | VGA | Up to 1920x1200 @ 60Hz |
| | VGA | DDI2 | DP Up to 4096x2160 @ 60Hz |
| Display | LVDS | eDP 1.3 | Up to 3840x2160 @ 60Hz |
| | LVDS | LVDS | Up to 1920x1200 @ 60Hz |
| | DDU DD | DD 4.2 / LIDMI 4.4b | DP Up to 4096x2160 @ 60H |
| | DDI1-DP | DP 1.2 / HDMI 1.4b | HDMI Up to 3840x2160 @ 30Hz |
| Security | TPM 2.0 (Infineon SLB9670) , Intel® AES | | |

PCOM-B641VG

MECHANICAL & ENVIRONMENT

| Dimension | 95 x 95mm | |
|--------------------------|---|--|
| Power DC IN | Nominal : +12V DC Wide range : +8VDC ~ +18VDC AT / ATX Mode | |
| Storage Temperature | -40°C to 85°C | |
| Operation Temperature | −40°C to 85°C | |
| Certification | Contact us | |
| MTBF | Over 120,000 hours at 40°C | |
| Vibration | Random 5Hz to 2KHz, 7.7 grms, 10min in each of 3 axes | |
| os | Windows 10 Linux CentOS 6 | |

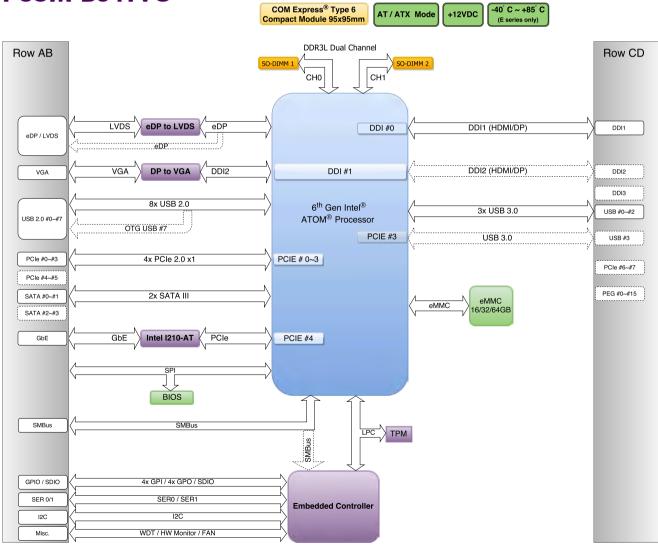
ORDERING GUIDE

| Product | Ordering P/N | Status |
|-----------------|--------------|-----------|
| PCOM-B641-E3950 | AB1-3F71Z | Available |
| PCOM-B641-E3940 | AB1-3F39Z | Available |
| PCOM-B641-E3930 | AB1-3F38Z | Available |
| PCOM-B641-N4200 | AB1-3F28Z | Available |
| PCOM-B641-N3350 | AB1-3F72Z | Available |

| Accessory | Ordering P/N | Status |
|---------------------------------------|--------------|-----------|
| Heat Sink for E3900 Series | B8308491 | Available |
| Heat Sink for N Series | B9971521 | Available |
| PCOM-C605 (MINI-ITX Carrier Board) | AB1-3998 | Available |
| PCOM-C640 (NANO-ITX Carrier Board) | AB1-3D18 | Available |
| PCOM-C600 (uATX ATX Carrier Board) | AB1-3761 | Available |

BLOCK DIAGRAM

PCOM-B641VG



PCOM-B700G

Intel® Pentium® / Xeon® D-1500 series Processor based on Type 7 COM Express® Rev3.0 module with DDR4 ECC/Non-ECC 3x SO-DIMM sockets, 1x PCle 3.0 x16, 1x PCle 3.0 x4, and 8x PCle 2.0 x1, TPM 2.0, and 2x KR





FEATURES

- Intel® Pentium® / Xeon® D-1500 series Processors
- Support DDR4-2133 MT/s ECC/Non-ECC SDRAM on three SO-DIMM sockets, up to 48GB
- Support USB 2.0/3.0, 2x SATA III,8x PCle 2.0 x1, 1x PCle 3.0 x4, and 1x PCle 3.0 x16





PCOM-B700G, a COM Express® Type 7 Basic Module designed with Intel® Pentium® and Xeon® D-1500 series processors. PCOM-B700G targets for Networking, Micro server applications. 10GbE LAN feature and three DDR4 SODIMM sockets support up to 2133MHz and 48GB memory.

General

| Product |
|--|
| Intel® Pentium® D1507 D1508 D1517 D1519 D-1527 D-1537 D-1539 D-1548 D-1557 D-157 |
| Processor D1507 D1508 D1517 D1519 D-1527 D-1537 D-1539 D-1548 D-1557 D-157 D-1 |
| D1507 D1508 D1517 D1519 D-1527 D-1537 D-1539 D-1548 D-1557 D-157 D-157 |
| Freq. 1.20 GHz 2.20 GHz 1.60 GHz 1.50 GHz 2.20 GHz 1.70 GHz 1.60 GHz 2.00 GHz 1.50 GHz 1.30 GHz 1.70 GHz 1.60 GHz 2.00 GHz 1.50 GHz 1.30 GHz 1.70 GHz 1.20 GHz 2.60 GHz 2.10 GHz 2.10 GHz 2.70 GHz 2.30 GHz 2.20 GHz 2.60 GHz 2.10 GHz 2.10 GHz 2.10 GHz 2.70 GHz 2.30 GHz 2.20 GHz 2.60 GHz 2.10 G |
| Turbo |
| Cache 3 MB 3 MB 6 MB 6 MB 6 MB 12 MB 12 MB 12 MB 12 MB 24 MB Processor Graphics Graphics Base Frequency Graphics Max Dynamic Frequency HW Decoding HW Acceleration Processor TDP 20 W 25 W 25 W 25 W 35 W 35 W 35 W 45 W 45 W 45 W 45 W 4 |
| Processor Graphics Graphics Base Frequency Graphics Max Dynamic Frequency Frequency HW Encoding HW Decoding HW Acceleration Processor TDP 20 W 25 W 25 W 35 W 35 W 45 W 45 W 45 W BIOS AMI Aptio5 UEFI BIOS ECC Memory Supported Yes Ye |
| Graphics Base Frequency Graphics Max Dynamic Frequency HW Encoding HW Acceleration Processor TDP 20 W 25 W 25 W 25 W 35 W 35 W 45 W 45 W 45 W 45 W 45 W 4 |
| Graphics Max Dynamic Frequency |
| Frequency |
| HW Encoding HW Decoding HW Acceleration Processor TDP 20 W 25 W 25 W 35 W 35 W 35 W 45 W 45 W 45 W BIOS AMI Aptio5 UEFI BIOS ECC Memory Supported Yes Ye |
| HW Acceleration Processor TDP 20 W 25 W 25 W 35 W 35 W 35 W 45 W 45 W 45 W 45 W 4 |
| Processor TDP 20 W 25 W 25 W 25 W 35 W 35 W 35 W 45 W 45 W BIOS AMI Aptio5 UEFI BIOS ECC Memory Supported Yes Yes Yes Yes Yes Yes Yes Yes Yes |
| BIOS AMI Aptio5 UEFI BIOS ECC Memory Supported Yes |
| ECC Memory Supported Yes |
| |
| |
| I/O Interface |
| SATA 2x SATA III |
| USB 4x USB 2.0 4x USB 3.0 |
| Ethernet Intel® Ethernet Controller I219AT for 1xGbE. 2x KR for 10GbE |
| GPIO 8 GPIO (4 GPI and 4 GPO) |
| Serial I/O Baud Rate : 400KHz |
| SMBus Baud Rate : 100KHz UAR 2 Serial Port (TX and RX) |
| PEG 1x PCle 3.0 x16 (1x16 / 2x8 / 4x4 / 1x8 + 2x4) |
| 8x PCle 2.0 x1 |
| PCI Express (8x1 / 4x2 / 2x4 / 1x4 + 2x2) 1x PCIE 3.0 x4 (1x4 / 2x2 / 4x1) |
| Security TPM 2.0 (Infineon SLB9665 , optional) , Intel® AES |

PCOM-B700G

MECHANICAL & ENVIRONMENT

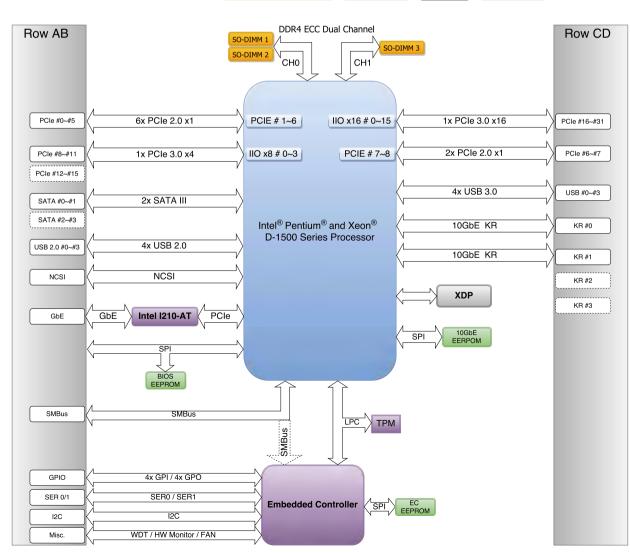
| Dimension | | 125mm x 95mm (4.92" x 3.74") | |
|----------------------------------|--|---|-----------|
| Power DC IN | Nominal : +12V DC AT / ATX Mode | | |
| Storage Temperature | 0°C ~ +60°C | | ; |
| Operating Temperature | $0^{\circ}\text{C} \sim +60^{\circ}\text{C}$ Extended : -40°C ~ +85°C (Processor dependent) | | |
| Certification | Contact us | | |
| MTBF | Over 100,000 hours at 40°C | | at 40°C |
| Vibration | Contact us | | |
| os | Lin | Windows 7/8/8.1/10 nux Fedora 22 / Ubuntu 15.04 / CentOS 7 | |
| Access | ory | Ordering P/N Status | |
| PCOM-B634VG Coo | ler | B9971410 | Available |
| PCOM-C609 (uATX ATX Carrier B | oard) | AB1-3D19 | Available |

| ORDERING | GUIDE | |
|----------------------------|---------------|-----------|
| Product | Ordering P/N | Status |
| PCOM-B700G-D1577 | AB1-3G83 | Available |
| PCOM-B700G-D1557 | Contact us | Available |
| PCOM-B700G-D1548 | AB1-3F53 | Available |
| PCOM-B700G-D1539 | AB1-3F52 | Available |
| PCOM-B700G-D1537 | AB1-3F52 | Available |
| PCOM-B700G-D1527 | AB1-3F51 | Available |
| PCOM-B700G-D1519 | AB1-3G80 | Available |
| PCOM-B700G-D1517 | AB1-3G77 | Available |
| PCOM-B700G-D1508 | AB1-3G78 | Available |
| PCOM-B700G-D1507 | AB1-3G79 | Available |
| Accessory | Ordering P/N | Status |
| PCOM-B700G Cooler | B9971570 | Available |
| PCOM-C700 (ATX Carrier Boa | ard) AB1-3F19 | Available |

BLOCK DIAGRAM

PCOM-B700G





PCOM-B701G

Intel® C3000 series Processor based on Type 7 COM Express® Rev3.0 module with DDR4 ECC/Non-ECC 3x SO-DIMM sockets, 20x PCIe Lanes, 4x KR/KX, GbE, NC-SI, TPM 2.0, and SATA 6 Gb/s





FEATURES

- New Type 7 Specification with Denverton server platform
- Support DDR4-2133 ECC/Non-ECC SDRAM on Three SO-DIMM Sockets, up to 48GB
- Four KR/KX(for10GbE) and one GbE Interfaces
- 4x USB 3.0/2.0, 2x SATA III, 12x PCle x1 Gen 2.0, 1x PCle x8 Gen 3.0







Portwell PCOM-B701G is designed with Intel® Atom® C3000 Processor and base on new Type 7 pin definition. It's built in with 10GbE Ethernet KR interface and DDR4 ECC SO-Dimm support which provide high CPU computing, excellent Ethernet performance. Extend PCIE Gen3 ports in PCOM-B701G can support high speed IO card for more applications. In the meantime, it's compatible with Type 6 carrier

| | General | | | | |
|--------------------------------|--|----------|---------------|----------|----------|
| Product | PCOM-B701G | | | | |
| Form Factor | Type 7, Compact Form Factor Com Express (125 x 95mm) | | | | |
| Processor | Intel® Atom® | | | | |
| Flocessoi | C3308 | C3508 | C3708 | C3808 | C3958 |
| Core | 2 | 4 | 8 | 12 | 16 |
| Freq. | 1.60 GHz | 1.60 GHz | 1.70 GHz | 2.00 GHz | 2.00 GHz |
| Turbo | 2.10 GHz | 1.60 GHz | 1.70 GHz | 2.00 GHz | 2.00 GHz |
| Cache | 4 MB | 8 MB | 16 MB | 12 MB | 16 MB |
| Processor Graphics | | | | | |
| Graphics Base Frequency | | | | | |
| Graphics Max Dynamic Frequency | | | NI/A | | |
| HW Encoding | N/A | | | | |
| HW Decoding | | | | | |
| HW Acceleration | | | | | |
| Processor TDP | 9.5W | 11.5W | 17W | 25W | 31W |
| BIOS | | | AMI UEFI BIOS | | |
| ECC Memory Supported | YES | | | | |
| Memory | Supports up to 128GB DDR4 2400 MT/s SDRAM | | | | |

| | I/O Interface | е |
|-------------|--------------------------------|-----------------------------------|
| SATA | 4 x S | ATA III |
| USB | | SB2.0 ISB3.0 |
| Ethernet | | l210IT X(10GbE) |
| | GPIO | 8 x GPIO |
| Serial I/O | I ² C | Baud rate: 400KHz |
| Serial I/O | SMBus | Baud rate: 100KHz |
| | UART | 2x UART |
| PEG | 1 PCle x8 (PEG) up to Gen3 (8. | 0 GT/s) configuration x4, x8, x16 |
| PCI Express | 8 x PCI | e 2.0 x2 |
| Display | N | I/A |
| Security | TPM 2.0 | (Option) |

PCOM-B701G

MECHANICAL & ENVIRONMENT

| Dimension | 125x95mm | |
|--------------------------|--|--|
| Power DC IN | 12V DC IN | |
| Storage Temperature | -40°C ~ 85°C | |
| Operating Temperature | -40°C ~ 85°C | |
| Certification | Contact us | |
| MTBF | Over 100,000 hours at both 35°C and 55°C | |
| Vibration | Random 5Hz to 2KHz, 7.7 grms, 10min in each of 3 axes | |
| os | Windows 7/8/8.1/10 Microsoft Windows 2008 R2 SP1/2012/2012 R2 Fedora 22 (kernel 4.0.4-301) Ubuntu 15.04 (kernel 3.11.6.4) | |

| ORDERING GUIDE | | | | |
|----------------------------|---------------|-----------|--|--|
| Product | Ordering P/N | Status | | |
| PCOM-B701G-C3308 | AB1-3G90 | Available | | |
| PCOM-B701G-C3508 | AB1-3G91 | Available | | |
| PCOM-B701G-C3708 | AB1-3G92 | Available | | |
| PCOM-B701G-C3808 | AB1-3G89 | Available | | |
| | | | | |
| Accessory | Ordering P/N | Status | | |
| PCOM-B701G Heatsink | Contact us | Available | | |
| PCOM-C700 (ATX Carrier Boa | ard) AB1-3F19 | Available | | |
| | | | | |

BLOCK DIAGRAM

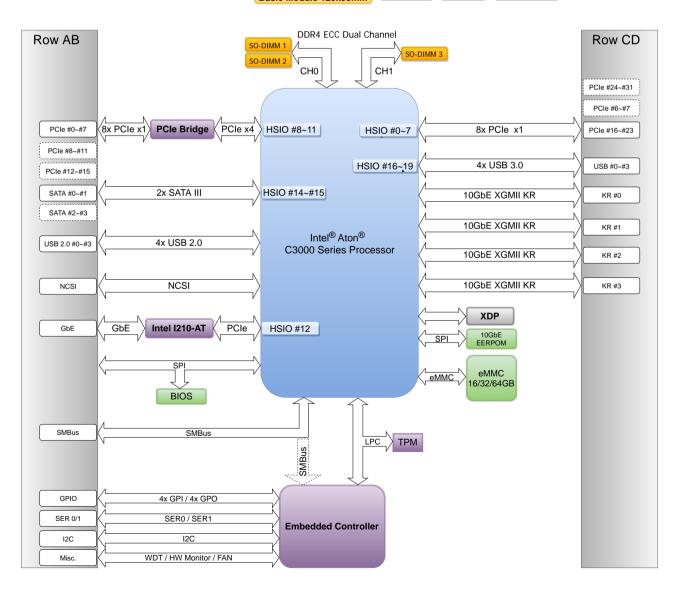
PCOM-B701G

COM Express® Type 7
Basic Module 125x95mm

AT Mode +

+12VDC

-40° C ~ +85° C



PCOM-C640 is NANO-ITX carrier board with triple display, Gigabit Ethernet, Audio, USB 3.0, SATA. It's a powerful carrier which is suitable for system.





FEATURES

- COM Express carrier board is compatible with the Portwell Type VI COM Express modules
- NANO-ITX form factor can meet most standard mounting spaces and provide more expansions and displays.
- Support Rear I/O, DP, RJ45, USB 2.0 & 3.0

Portwell PCOM-C640 is a NANO-ITX form factor carrier with COM Express Type VI row connectors. It's suitable for evaluation testing of Portwell's Type VI COM Express modules for 1U Server system. We also provide carrier board design guide for your own carrier board development as a reference. With PCOM-C640 carrier board, Portwell now has various carriers in different form factors to help customers on developing new platform for both board and system perspectives. Customers can easily begin to develop on new application with Portwell's COM Express Type VI module.

| Product |
|--------------------------------|
| Form Factor |
| Processor |
| Core |
| Freq. |
| Turbo |
| Cache |
| Processor Graphics |
| Graphics Base Frequency |
| Graphics Max Dynamic Frequency |
| HW Encoding |
| HW Decoding |
| HW Acceleration |
| Processor TDP |
| BIOS |
| ECC Memory Supported |
| Memory |
| |

| I/O Interface | | | | |
|---------------|--------------------------|------|-----------------------|--|
| SATA | 2x SATA III | | | |
| USB | 1 x USB2.0 2 x USB3.0 | | | |
| Ethernet | 2 x GbE | | | |
| | GPIO | | 8 GPIO | |
| Serial I/O | I ² C | | base on module design | |
| Serial I/O | SMBus | | base on module design | |
| | UART | | 2x UART | |
| PEG | N/A | | | |
| PCI Express | 1x PCle x1 | | | |
| | CRT | CRT | 2560 x 1600 | |
| Display | LVDS | LVDS | 1920x1200 | |
| | LIDAM | DP | 3840 x 2160 | |
| | HDMI | HDMI | N/A | |
| Security | | N/A | | |

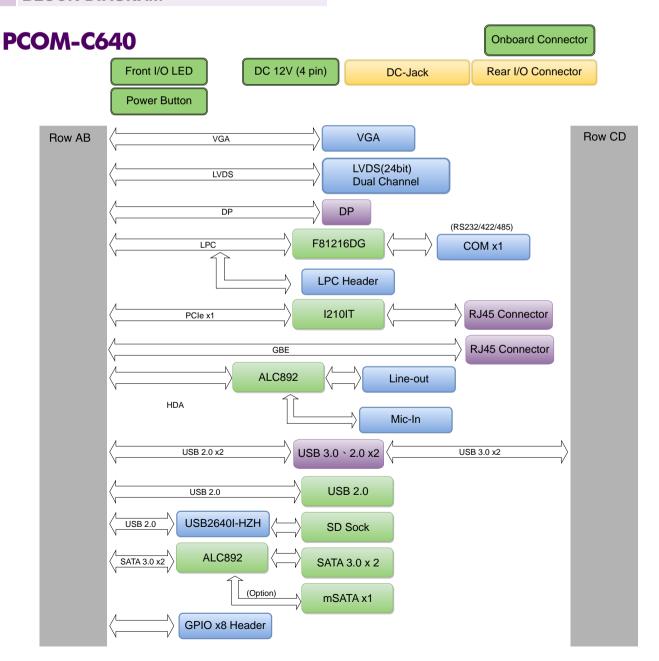
MECHANICAL & ENVIRONMENT

| Dimension | 120 x 120mm | |
|--------------------------|----------------------------------|--|
| Power DC IN | 12V DC IN | |
| Storage Temperature | −20°C to 85°C | |
| Operation Temperature | 0°C to 55°C | |
| Certification | Contact us | |
| MTBF | Over 100,000 hours at both 40° C | |
| Vibration | N/A | |
| os | Depend on Module | |

ORDERING GUIDE

| Product | Ordering P/N | Status |
|-----------|--------------|-----------|
| PCOM-C640 | AB1-3D18Z | Available |

BLOCK DIAGRAM







FEATURES

- COM Express® carrier board is compatible with the Portwell Type VI COM Express® modules
- Mini-ATX form factor meets most standard mounting spaces and provides more expansions slots

Portwell PCOM-C605 is designed with Mini-ITX form factor with COM Express Type VI row connectors, suitable for evaluation testing of Portwell's Type VI COM Express modules on PCI-E, PEG, VGA/LVDS, USB, SATA, and CFEX with SATA and SPI interface. We also provide carrier board design guides for your own carrier board development reference.

This new version of the PCOM-C605 Reference Carrier Board is 100% compatible with the recently released PICMG COM Express Carrier Design Guide and provides a full complement of I/O interfaces, debugging tools, and peripheral devices such as Super I/O and audio code that may be required on the custom carrier board. The full schematics and mechanical drawings of the PCOM-C605 are available for testing to allow customers to immediately begin their own carrier board design effort. A complete Starter Kit is also available, which includes the COM Express module of choice, the PCOM-C605 reference carrier board, thermal solution, documentation.

| General | | |
|--------------------------------|------------------------|--|
| Product | PCOM-C605 | |
| Form Factor | Mini-ITX (170 x 170mm) | |
| Processor | | |
| Core | | |
| Freq. | | |
| Turbo | | |
| Cache | | |
| Processor Graphics | | |
| Graphics Base Frequency | | |
| Graphics Max Dynamic Frequency | N/A | |
| HW Encoding | | |
| HW Decoding | | |
| HW Acceleration | | |
| Processor TDP | | |
| BIOS | | |
| ECC Memory Supported | | |
| Memory | | |

| I/O Interface | | | | |
|---------------|---|-----------------------|----|-----------------------|
| SATA | 1 x SATA II 2 x SATA III 1 x CFEX | | | |
| USB | 4 x USB 3.0/2.0 | | | |
| Ethernet | 2 x GbE | | | |
| | GPIO | 8 GPIO | | 8 GPIO |
| Serial I/O | I ² C | base on module design | | base on module design |
| Serial I/O | SMBus | | | base on module design |
| | UAR | | | 1x UAR |
| PEG | 1 x PCle x16 | | | |
| PCI Express | 2 x PCle x1 Golden Finger | | | |
| | VGA | VGA | 4 | 2560 x 1600 |
| Display | LVDS | LVDS | S | 1920x1200 |
| | HDMI | | | 3840 x 2160 |
| | | | 11 | 3840 x 2160 |
| Security | N/A | | | |

ODDEDING CHIDE

MECHANICAL & ENVIRONMENT Dimension 120 x 120mm Power DC IN 12V DC IN Storage Temperature -40°C to 85°C Operation Temperature -40°C to 85°C Certification Contact us

Over 100,000 hours at both 40° C

N/A

Depend on Module

| OKDEKING COIDE | | | | |
|----------------|--------------|-----------|--|--|
| Product | Ordering P/N | Status | | |
| PCOM-C605 | AB1-3998 | Available | | |

BLOCK DIAGRAM

MTBF

os

Vibration

PCOM-C605 R2

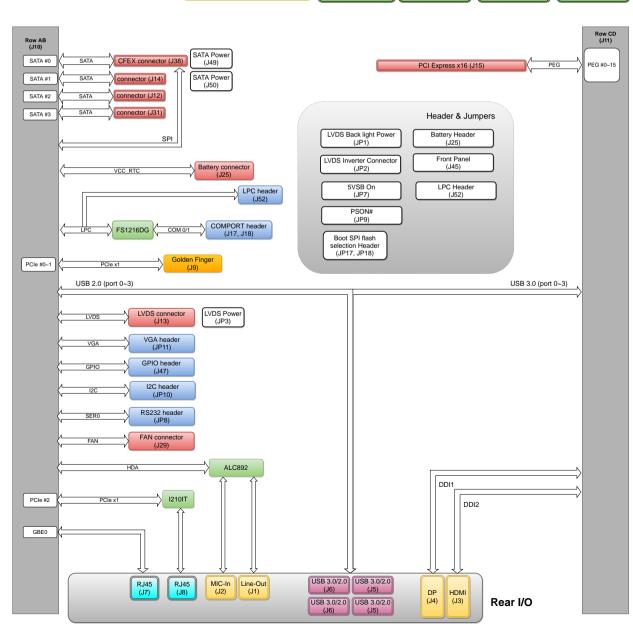
COM Express Type 6
Carrier Board

Mini-ITX Form Factor

-40 ~ +85°C

ATX PSU Connector

12V DC in



PCOM-C700G

ATX Form Factor Evaluation Carrier Board for Type 7 COM Express® Rev3.0 module with 4x 10GbE Support





FEATURES

- 4x 10GbE Support
- Consoles Redirection Support
- BMC AST2500 Support

Portwell PCOM-C700 is designed with ATX form factor with COM Express Type VII row connectors; it's suitable for evaluation testing of Portwell's Type VII COM Express modules with 4x USB 3.0, 28x PCIe lanes, 4x 10 Gigabit Ethernet, and BMC AST2500 support. Portwell is able to provide carrier board design guide for customer to design their carrier board as a reference. This can shorten customer's carrier board developing time and make the development quickly and easily. The PCOM-C700 provides COM Express Type VII support in addition to suit wide range of device connectivity for prototype and flexibility.

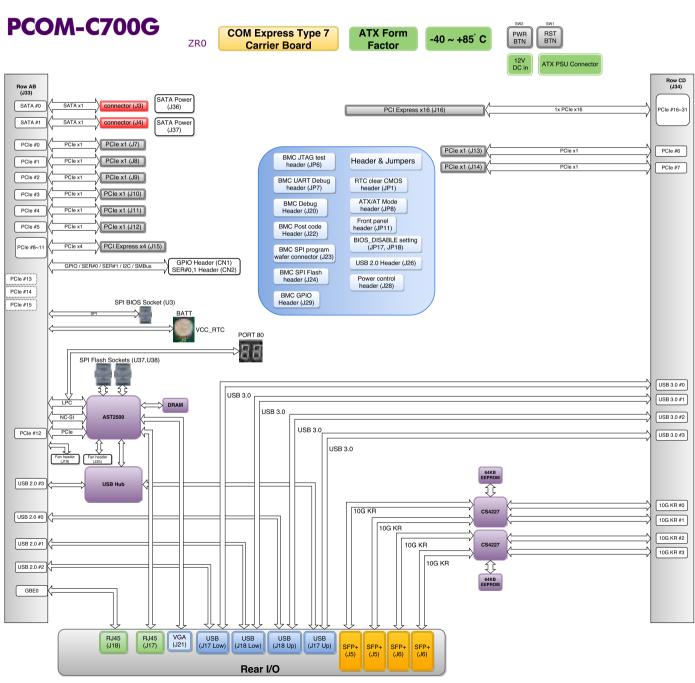
| General | | |
|--------------------------------|----------------------------|--|
| Product | PCOM-C700 | |
| Form Factor | Type 7, ATX (305 × 244 mm) | |
| Processor | | |
| Core | | |
| Freq. | | |
| Turbo | | |
| Cache | | |
| Processor Graphics | | |
| Graphics Base Frequency | | |
| Graphics Max Dynamic Frequency | Depends on Module | |
| HW Encoding | | |
| HW Decoding | | |
| HW Acceleration | | |
| Processor TDP | | |
| BIOS | | |
| ECC Memory Supported | | |
| Memory | | |

| I/O Interface | | | | |
|---------------|-------------------------------|-----------------------|--|--|
| SATA | 2 x SATA III | | | |
| USB | 4 x USB3.0 (Depend on Module) | | | |
| Ethernet | 4x 10GbE 1x Gbe | | | |
| | GPIO | 8 GPIO | | |
| Serial I/O | I ² C | Base on module design | | |
| Serial I/O | SMBus | Base on module design | | |
| | UART | 2 x UART | | |
| PEG | 1x PCle x16 | | | |
| PCI Express | 1x PCIe x4 8x PCIe x1 | | | |
| Display | VGA | 2560 x 1536 @ 24bpp | | |
| Security | N | 'A | | |

PCOM-C700

MECHANICAL & ENVIRONMENT Dimension 305x244mm Power DC IN 12V DC IN Storage -40°C to 85°C Temperature Operating Temperature 0°C to 60°C Certification Contact us MTBF N/A Vibration N/A os Depends on Module

| ORDERING G | UIDE | |
|---|--------------|-----------|
| Product | Ordering P/N | Status |
| PCOM-C700.Support TYPE VII. ATX Form Factor.COM Express Carrier Board | AB1-3F19Z | available |







FEATURES

- Intel® Atom® Processor E3800 Series(Bay Trail)
- On Board DDR3L SDRAM up to 8GB
- eMMC up to 64GB
- DP/HDMI and LVDS





PQ7-M106 is designed with Intel® Atom® Processor E3800 Series and qualified components for wide-temp support. This series also supports LVDS, Dual-Channel DDR3L, as well as eMMC soldered on board to be a cost effective collection.

| General | | | | | | |
|--------------------------------|--|---|---|---|--|--|
| Product | PQ7-M106 | | | | | |
| Form Factor | | Qseven® 2.0 | , 70 x 70 mm | | | |
| Processor | Intel® Atom® | | | | | |
| FIOCESSOI | E3845 | E3827 | E3825 | E3815 | | |
| Core | 4 | 2 | 2 | 1 | | |
| Freq. | 1.91 GHz | 1.91 GHz 1.75 GHz 1.33 GHz 1.46 GHz | | | | |
| Turbo | N/A N/A N/A | | | | | |
| Cache | 2MB 1MB 1MB 512KB | | | | | |
| Processor Graphics | Intel® HD Graphics for Intel Atom® Processor Z3700 Series | Intel® HD Graphics for Intel Atom®Processor Z3700 Series | Intel® HD Graphics for Intel Atom®Processor Z3700 Series | Intel® HD Graphics for Intel Atom®Processor Z3700 Series | | |
| Graphics Base Frequency | 542 MHz 542 MHz 533 MHz 400 MHz | | | | | |
| Graphics Max Dynamic Frequency | 792 MHz | 792 MHz 792 MHz 533 MHz 400 MHZ | | | | |
| HW Encoding | | H.2 | 264 | | | |
| HW Decoding | | H.264, JPEG, MJPEG, MV | VC, MPEG-2, WMV9, VC1 | | | |
| HW Acceleration | DX*11, OpenGL* 3.0 (OGL 3.0), OpenCL* 1.2 (OCL 1.2), OpenGLES* 2.0(OGLES* 2.0) | | | | | |
| Processor TDP | 10W 8W 6W 5W | | | | | |
| BIOS | AMI Aptio5 BIOS | | | | | |
| ECC Memory Supported | NO | | | | | |
| Memory | On Board DDR3L Non-ECC up to 8GB | | | | | |

| | | I/O Interface | |
|-------------|-----------------------------------|--------------------------|-------------------|
| SATA | 2x SATA II | | |
| USB | 6 x USB2.0 with 1x Opt. to USB3.0 | | |
| Ethernet | | 1x Gbe (Intel® I210IT) | |
| | LPC | | 1x LPC |
| Serial I/O | I ² C | | Baud rate: 400KHz |
| Serial I/O | SMBus | | Baud rate: 100KHz |
| | UART 1x UART | | 1x UART |
| PEG | N/A | | |
| PCI Express | | 1x PCIe x4 8x PCIe x1 | |
| | LVDS | eDP | 2560x1600 |
| Display | y HDMI | DP | 2560x1600 |
| | T IDIVII | HDMI | 1920x1080 |
| Security | | N/A | |

MECHANICAL & ENVIRONMENT

| Dimension | 70 x 70mm |
|--------------------------|--------------------|
| Power DC IN | 5V DC ±5% |
| Storage Temperature | -40°C to 85°C |
| Operating Temperature | −40°C to 85°C |
| Certification | Contact us |
| MTBF | NA |
| Vibration | NA |
| os | Windows 7/8/8.1/10 |

ORDERING GUIDE

| Product | Ordering P/N | Status |
|---------------------------------------|--------------|-----------|
| PQ7-M106-E3845-4G-8G | AB7-3031Z | Available |
| PQ7-M106-E3827-4G-8G | Contact us | Available |
| PQ7-M106-E3825-2G-4G | Contact us | Available |
| PQ7-M106-E3815-2G-NA | AB7-3045Z | Available |
| PQ7-M106-E3805-2G-4G | Contact us | Available |
| Other Memory/Storage Configuration | Contact us | Available |
| Accessory | Ordering P/N | Status |
| Heat Spreader | B8308530 | Available |
| Heat Sink Kit | B8309050 | Available |
| PQ7-C201 | AB1-3B45 | Available |

BLOCK DIAGRAM

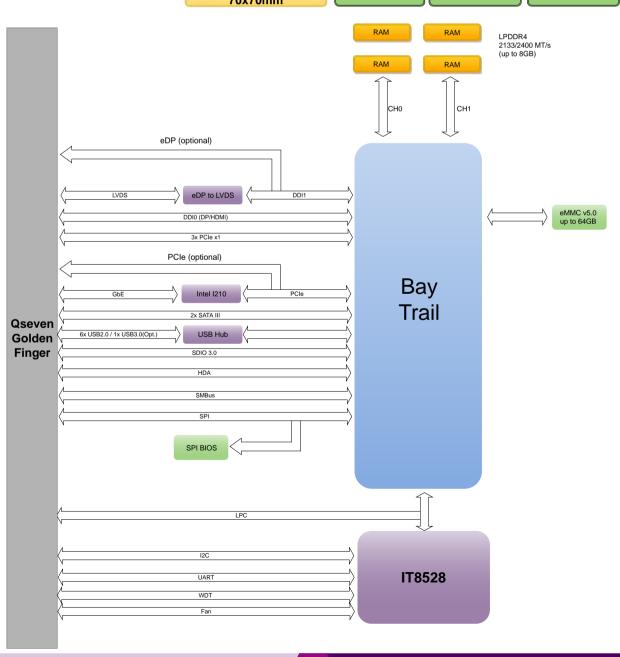
PQ7-M106

QSEVEN 2.0 70x70mm

AT/ATX Mode

-40° C~ +85° C

5V±5% DC-in







FEATURES

- On Board LPDDR4 DRAM and up to 8GB
- 24-bit LVDS, HDMI/DP output
- Four PCI Express lanes
- Support three USB 3.0 or four USB 2.0
- On Board eMMC 5.0 (Optional)





PQ7-M108 is designed with Intel® Atom®/ Pentium®/ Celeron® processors (Apollo Lake) which featured with higher graphic performance and wider memory bandwidth than the previous platform.

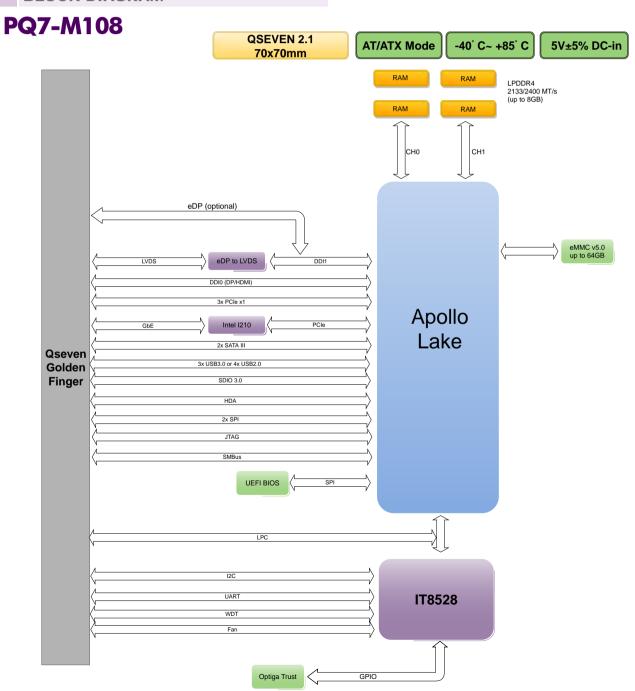
Benefit from Intel Apollo Lake industrial grade processor design, the operating temperature supports -40°C to 85°C. With qualified industrial-grade components selecting, PQ7-M108 is aimed to be widely applied on automation, security, transportations and so to different kinds of harsh environment applications.

| | | Ger | neral | | |
|--------------------------------|--|------------------------|----------------------------|------------------------|------------------------|
| Product | PQ7-M108 | | | | |
| Form Factor | | | Qseven® 2.1, 70 x 70 mm | | |
| Processor | | Intel® Atom® | | Intel® P | 'entium® |
| 110063301 | E3950 | E3940 | E3930 | N4200 | N3350 |
| Core | 4 | 4 | 2 | 4 | 2 |
| Freq. | 1.60 GHz | 1.60 GHz | 1.30 GHz | 1.10 GHz | 1.10 GHz |
| Turbo | 2.00 GHz | 1.80 GHz | 1.80 GHz | 2.50 GHz | 2.40 GHz |
| Cache | 2MB | 2MB | 2MB | 2MB | 2MB |
| Processor Graphics | Intel® HD Graphics 505 | Intel® HD Graphics 500 | Intel® HD Graphics 500 | Intel® HD Graphics 505 | Intel® HD Graphics 500 |
| Graphics Base Frequency | 500 MHz 400 MHz 400 MHz 200 MHz 200 MHz | | | | 200 MHz |
| Graphics Max Dynamic Frequency | 650 MHz | 600 MHz | 550 MHz | 750 MHZ | 650 MHZ |
| HW Encoding | | HE | EVC, H.264, MVC, VP8, MJPE | EG | |
| HW Decoding | | HEVC, H.264 | , MVC, MPEG2, VP9, VC1, W | MV9, MJPEG | |
| HW Acceleration | Intel® Gen 9 LP Graphics supporting DirectX 12, OpenGL 4.3 OpenGL 2.0, OpenGL ES 3.0 | | | | |
| Processor TDP | 12W 9.5W 6.5W 6W 6W | | | | 6W |
| BIOS | AMI Aptio5 BIOS | | | | |
| ECC Memory Supported | YES | | | | |
| Memory | On Board LPDDR4 DRAM and up to 8GB | | | | |

| | | I/O Interface | |
|-------------|----------------------------|--|---------------------|
| SATA | 2x SATA III | | |
| USB | 3 x USB 3.0 4 x USB 2.0 | | |
| Ethernet | | 1x 10/100/1000 GbE (Intel® I210-AT/IT) | |
| | GPIO | | N/A |
| Serial I/O | I ² C | | Baud rate: 400KHz |
| Serial I/O | SMBus | | Baud rate: 100KHz |
| | UART 1x UART | | |
| PEG | N/A | | |
| PCI Express | | 4 x PCle x1 Gen2 | |
| | LVDS | eDP | 3840 x 2160p @ 60Hz |
| Display | HDMI | DP | 4096 x 2160 @ 60Hz |
| | FIDIVII | HDMI | 3840 x 2160p @ 30Hz |
| Security | | N/A | |

| MECHANICAL & ENVIRONMENT | | |
|--------------------------|--|--|
| Dimension | 70 x 70mm | |
| Power DC IN | +5VDC ± 5% | |
| Storage Temperature | -40°C to 85°C | |
| Operating Temperature | -40°C to 85°C | |
| Certification | Contact us | |
| MTBF | Contact us | |
| Vibration | Contact us | |
| os | Windows 10 IoT Enterprise/ Windows 10 IOT Core | |

| ORDERING | G GUIDE | |
|----------------------|---|-----------|
| Product | Ordering P/N | Status |
| PQ7-M108-N3350-4G-8G | AB7-3019Z | Available |
| PQ7-M108-N4200-4G-8G | AB7-3054Z | Available |
| PQ7-M108-E39xx-xG-xG | Contact us Available | |
| Accessory | Ordering P/N Status | |
| Heat Spreader | B8308940 (for N3350/N4200) B8309030 (for E3930/E3940/E3950) Available | |
| Heat Sink Set | B8308970 (for N3350/N4200) B8308980 (for E3930/E3940/E3950) Available | |
| PQ7-C201 | AB1-3B45 Available | |



PEM-E203VLA

Intel® ATOM® E3800 series processor based on form factor module ETX® 3.0 specification with DDR3L optional ECC/ Non-ECC Memory down, VGA, LVDS, Gigabit Ethernet, IDE, PCI, ISA, Parallel Port, SATA and USB





FEATURES

- ETX tailor-made modular architecture speeds up time-to-market
- 10W TDP for easy fan-less design
- SATA and IDE interface provide best cost effective functions for market
- Support VGA, LVDS and Display-port interface
- On Board DDR3L optional ECC/Non-ECC Memory up to 4GB





Portwell PEM-E203VLA is designed with Intel® ATOM® E3800 series processor. PEM-E203 supports dual 24bit LVDS, and 10W TDP processor is suitable for supermarket, healthy and industrial weighing scale applications which has equipped with dual monitors nowadays. PEM-E203 is capable of driving thermal printer, barcode scanner etc. via Serial and USB interfaces for achieving self-service along with weighing scale.

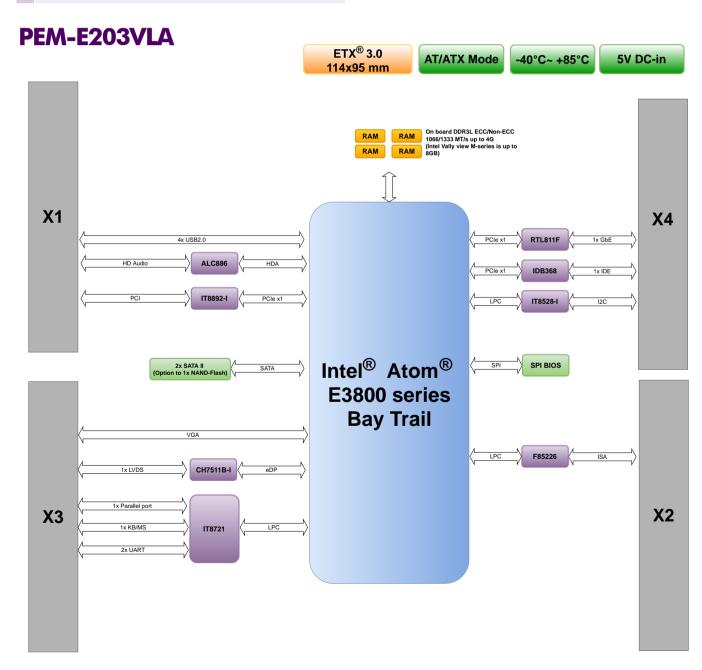
| | | General | | | | |
|--------------------------------|---|---|-----------------------|---------|--|--|
| Product | PEM-E203VLA | | | | | |
| Form Factor | | ETX 3.01, | 114x95 mm | | | |
| Processor | | Intel® | Atom® | | | |
| 1 10003301 | E3845 | E3827 | E3825 | E3815 | | |
| Core | 4 | 2 | 2 | 1 | | |
| Freq. | 1.91 GHz | 1.91 GHz 1.75 GHz 1.33 GHz 1.46 GHz | | | | |
| Turbo | N/A | | | | | |
| Cache | 2MB 1MB 1MB 512KB | | | | | |
| Processor Graphics | Intel® HD Graphics for Intel Atom® Processor Z3700 Series | | | | | |
| Graphics Base Frequency | 542 MHz | 542 MHz | 533 MHz | 400 MHz | | |
| Graphics Max Dynamic Frequency | 792 MHz | 792 MHz | 533 MHz | 400 MHZ | | |
| HW Encoding | | н | 264 | | | |
| HW Decoding | | H.264, JPEG, MJPEG, M | VC, MPEG-2, WMV9, VC1 | | | |
| HW Acceleration | DX x11 | DX x11, OpenGL x3.0 (OGL 3.0), OpenCL x1.2 (OCL 1.2), OpenGLES x2.0(OGLES x2.0) | | | | |
| Processor TDP | 10W | 8W | 6W | 5W | | |
| BIOS | AMI Aptio5 BIOS | | | | | |
| ECC Memory Supported | | ١ | ⁄es | | | |
| Memory | On Board DDR3L optional ECC/Non-ECC Memory up to 4GB (Intel® Valleyview I-series is up to 8GB for E3845 & E3827 only) | | | | | |

| | | I/O Interface | |
|-------------|--|---------------|-------------------|
| SATA | 2x SATA II (Option to 1x NAND-Flash) | | |
| USB | 4x USB2.0 | | |
| Ethernet | 1x Realtek® RTL811F-CG FastEthernet Wake-on-LAN and remote wake-up support | | |
| | GPIO | | N/A |
| Serial I/O | I ² C | | Baud rate: 400KHz |
| Serial I/O | SMBus | | Baud rate: 100KHz |
| | UART 2x UART | | |
| PEG | N/A | | |
| PCI Express | | N/A | |
| | VGA | VGA | 2048 x 1536 |
| Display | LVDS | eDP | 1600 x 1200 |
| Display | piay HDMI | DP | N/A |
| | HUMI | HDMI | N/A |
| Security | | Contact us | |

PEM-E203VLA

| MECH | ANICAL & ENVIRONMENT | |
|--------------------------|--|--|
| Dimension | 114 x 95 mm | |
| Power DC IN | 5V,3V, 5VSB, VBAT, AT/ATX mode | |
| Storage Temperature | -40°C~ +85°C | |
| Operating Temperature | -40°C~ +85°C | |
| Certification | Contact us | |
| MTBF | Over 120,000 hours at both 35° C and 55° C) | |
| Vibration | Random 5Hz to 2KHz, 7.7 grms, 10min in each of 3 axes | |
| OS | Windows 7 / Windows Embedded Standard 7/ Windows 8 / Fedora 18 uBuntu 13 | |

| ORDERING GUIDE | | | | |
|----------------------|--------------|-----------|--|--|
| Product | Ordering P/N | Status | | |
| PEM-E203VLA-E3815-2G | AB1-3C29 | Available | | |
| PEM-E203VLA-E3825-2G | AB1-3C52 | Available | | |
| PEM-E203VLA-E3827-2G | AB1-3B58 | Available | | |
| PEM-E203VLA-E3845-2G | AB1-3C28 | Available | | |
| PEM-E203VLA-E3845-4G | AB1-3D67 | Available | | |
| Accessory | Ordering P/N | Status | | |
| PEM-C200 | AB1-3246 | Available | | |
| Heat spreader | B8307620 | Available | | |
| Heat Sink | B8308990 | Available | | |



PEM-E205VLA

Vortex DX3 processor based on ETX 3.02 module with DDR3 Memory down, VGA, LVDS, PCI, ISA, IDE and USB





FEATURES

- Support DDR3 Memory-down, up to 2GB
- One VGA and LVDS, FastEthernet interface
- Support industrial temperature -40°C~85°C



Portwell PEM-E205VLA is designed with DMP 1.0 GHz Dual-Core processor, with less than 5W overall TDP, PCI and dual 24bit LVDS support it is suitable for industrial and transportation applications. Expansion for the PEM-E205VLA ETX module includes ISA interface with controllers integrated into processor-enhancing capabilities to support 8/16-bit ISA device with Zero-Wait-State. In addition, the module supports dual displays, VGA and LVDS with greater graphic performance compared to its previous generation. The resolution for one display interface supports up to 1920x1440@60Hz with 234MHz video clock, and the other, 1920x1200, 1x DVO (24bits) and 1x D-SUB or 2x DVO (12bits x2).

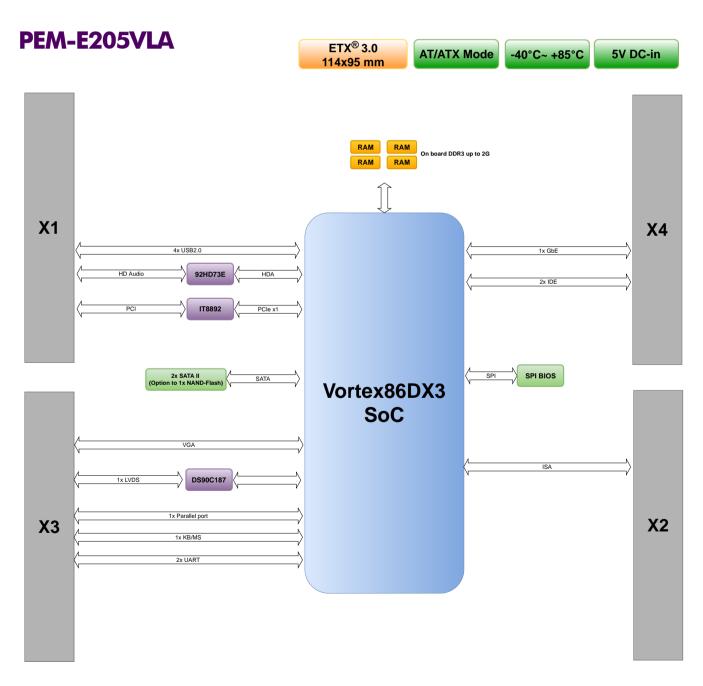
| General | | | | | | |
|-----------------------------------|--|--|--|--|--|--|
| Product | PEM-E205VLA | | | | | |
| Form Factor | ETX 3.02, 114x95 mm | | | | | |
| Processor | Vortex86DX3 SoC | | | | | |
| Core | 2 | | | | | |
| Freq. | 1 GHz | | | | | |
| Turbo | N/A | | | | | |
| Cache | 256KB | | | | | |
| Processor Graphics | GPU integrated in Vortex 86DX3 | | | | | |
| Graphics Base Frequency | N/A | | | | | |
| Graphics Max Dynamic Frequency | N/A | | | | | |
| HW Encoding | Contact us | | | | | |
| HW Decoding | H.264 | | | | | |
| HW Acceleration | Contact us | | | | | |
| Processor TDP | 5W | | | | | |
| BIOS | AMI BIOS | | | | | |
| ECC Memory Supported | Yes | | | | | |
| Memory | Yes | | | | | |
| Memory | On board DDR3 memory up to 2GB (optional with ECC) | | | | | |
| | I/O Interface | | | | | |
| SATA | 2x SATA II (Option to 1x NAND-Flash) 1x IDE | | | | | |
| USB | 4x USB2.0 | | | | | |
| Ethernet | 1v PTI 8110I ChE controller | | | | | |

| I/O Interface | | | | | |
|---------------|--|------------|-------------------|--|--|
| SATA | 2x SATA II (Option to 1x NAND-Flash) 1x IDE | | | | |
| USB | | 4x USB2.0 | | | |
| Ethernet | 1x RTL8119I GbE controller | | | | |
| | GPIO | | N/A | | |
| Serial I/O | I ² C | | Baud rate: 400KHz | | |
| Serial I/O | SMBus | | Baud rate: 100KHz | | |
| | UART | | 2x UART | | |
| PEG | N/A | | | | |
| PCI Express | N/A | | | | |
| | VGA | VGA | 1920x1440@ 60Hz | | |
| Display | LVDS | eDP | 1920×1200 | | |
| Display | HDMI | DP | NA | | |
| | i ibivii | HDMI | NA | | |
| Security | | Contact us | | | |

PEM-E205VLA

| MECH | ANICAL & ENVIRONMENT |
|--------------------------|--|
| Dimension | 114x95 mm |
| Power DC IN | 5V,3V, 5VSB, VBAT, AT/ATX mode |
| Storage Temperature | -40°C~ +85°C |
| Operating Temperature | -40°C~ +85°C |
| Certification | Contact us |
| MTBF | Over 120,000 hours at both 35° C and 55° C) |
| Vibration | Random 5Hz to 2KHz, 7.7 grms, 10min in each of 3 axes |
| os | Windows for Workgroups 3.11 / Windows XP Embedded Standard 2009 and higher / Windows 7 Embedded Linux (Kernel >= 2.4)/ RTOS32 MS DOS 6.22 / FreeDOS |

| ORDERING GUIDE | | | | |
|----------------|--------------|-----------|--|--|
| Product | Ordering P/N | Status | | |
| PEM-E205VLA | AB1-3D65 | Available | | |
| | | | | |
| Accessory | Ordering P/N | Status | | |
| PEM-C200 | AB1-3246 | Available | | |
| Heat spreader | B8308090 | Available | | |
| Heat Sink | B8308090 | Available | | |
| | | | | |



PSMC-M1011

SMARC module by SMARC 2.0 based on Intel® Atom® / Pentium® / Celeron® processors (Apollo Lake) with LPDDR4 SDRAM up to 8GB, 24bit LVDS, DP, HDMI



Product



FEATURES

- Intel® Atom® / Pentium® / Celeron® processors (Apollo Lake)
- On Board LPDDR4 SDRAM and up to 8GB
- Triple display support (18/24-bit LVDS, DP++, HDMI)
- Four PCI Express lanes, two USB 3.0 and six USB 2.0
- One SATA 3.0, on Board eMMC 5.0

PSMC-M1011





PSMC-M101 is designed with Intel® Atom®/ Pentium®/ Celeron® processors (Apollo Lake) processors featured with higher graphic performance and wider memory bandwidth than the previous platform.

Based on Intel Apollo Lake industrial grade processor support, industrial components selecting, and with wide-voltage input design adding on board, PSMC-M101 not only aims at various applications (i.e. automation, fire security, transportations), but is also set to support kinds of harsh environment with a stable power input.

General

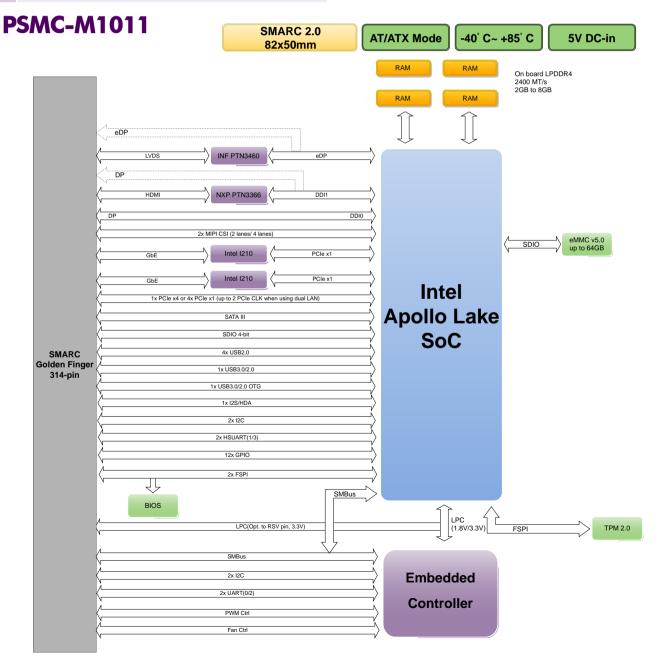
| Form Factor | | SMARC™ 2.0, 82x50mm | | | | | |
|-----------------------------|-----------|--|------------------------|------------|------------------------------|------------------------|------------------------|
| Processor | | Intel® Atom® | | | Intel® Pentium® | | |
| | | E3950 | E3940 | | E3930 | N4200 | N3350 |
| Core | | 4 | 4 | | 2 | 4 | 2 |
| Freq. | | 1.60 GHz | 1.60 GHz | | 1.30 GHz | 1.10 GHz | 1.10 GHz |
| Turbo | | 2.00 GHz | 1.80 GHz | | 1.80 GHz | 2.50 GHz | 2.40 GHz |
| Cache | | 2MB | 2MB | | 2MB | 2MB | 2MB |
| Processor Grap | phics | Intel® HD Graphics 505 | Intel® HD Graphics 500 | Intel® | HD Graphics 500 | Intel® HD Graphics 505 | Intel® HD Graphics 500 |
| Graphics Base | Frequency | 500 MHz | 400 MHz | | 400 MHz | 200 MHz | 200 MHz |
| Graphics Max I Frequency | Dynamic | 650 MHz | 600 MHz | | 550 MHz | 750 MHZ | 650 MHZ |
| HW Encoding | | | | HEVC, H.2 | 64, MVC, VP8, MJPE | EG | |
| HW Decoding | | | HEVC, H.2 | 64, MVC, N | MPEG2, VP9, VC1, W | MV9, MJPEG | |
| HW Acceleration | on | Intel® Gen 9 LP Graphics supporting DirectX 12, OpenGL 4.3 OpenCL 2.0, OpenGL ES 3.0 | | | | 0 | |
| Processor TDP | • | 12W | 9.5W | | 6.5W | 6W | 6W |
| BIOS | | AMI Aptio5 BIOS | | | | | |
| ECC Memory S | Supported | YES | | | | | |
| Memory | | On Board LPDDR4 DRAM and up to 8GB | | | | | |
| | | I/O Interface | | | | | |
| SATA | | 2x SATA III | | | | | |
| USB | | 6x USB2.0 (w/1x OTG) 2x USB 3.0 (w/1x OTG) | | | | | |
| Ethernet | | 2x 10/100/1000 GbE (Intel® I210AT (Commercial) / I210IT (Industrial) | | | | | |
| | | GPIC |) | | 12 GPIO | | |
| Serial I/O | | I ² C | | | Baud rate: 400KHz | | |
| | | SMBı UAR | | | Baud rate: 100KHz 2x UART | | |
| PEG | | N/. | | N/A | | | |
| PCI Express | | 4 x PCIe x1 Gen2 2x PCIe CLK to Golden Finger when using dual LAN ports | | | | | |
| LVDS | | eDP | | | 3840 x 2160p @ 60Hz | | |
| Display | | НОМІ | | | DP 4096 x 2160 @ 60Hz | | |
| Socurity | | | HDMI TPM 2.0 (O | | | | |
| Security | | | | I FIVI Z.U | (Option) | | |
| | | | | 45 | | | |

PSMC-M1011

MECHANICAL & ENVIRONMENT Dimension 82x50mm

| 2 | 02/06/11111 |
|--------------------------|--|
| Power DC IN | +5VDC ± 5% AT / ATX Mode |
| Storage Temperature | Commercial: 0°C to +60°C Industrial: -40°C to +85°C |
| Operating Temperature | Commercial: 0°C to +60°C Industrial: -40°C to +85°C |
| Certification | Contact us |
| MTBF | Contact us |
| Vibration | Contact us |
| os | Windows 10 Enterprise Windows 10 IoT Linux |

| ORDERING GUIDE | | | | |
|----------------------------------|------------|--------------|-----------|--|
| Product | | Ordering P/N | Status | |
| PSMC-M1011-E3950-4G-8G | | AB7-3051Z | Available | |
| PSMC-M1011-N3350-4G-8G | | Contact us | Available | |
| PSMC-M1011-N4200-4G-8G | | Contact us | Available | |
| PSMC-M1011-Exxx-xG-xG | Contact us | | Available | |
| Accessory | | Ordering P/N | Status | |
| PSMC-M1011 Heat Spreader (APL-N) | | B8309290 | Available | |
| PSMC-M1011 Heat Sink Set (APL-N) | | B8309280 | Available | |
| PSMC-M1011 Heat Spreader | (APL-I) | B8309270 | Available | |
| PSMC-M1011 Heat Sink Set (| (APL-I) | B8309260 | Available | |
| PSMC-C301 | | AB7-3078 | Available | |
| | | | | |



Signal integrity is tested and assured

The Signal Integrity Lab (SI) concentrates its efforts on ensuring reliable quality of our PCB design. With advanced software, Portwell can repair discrepancies via Signal Integrity (SI), Power Integrity (PI) and EMI (Electromagnetic Interference) before gerber out. The benefits of SI not only reduces re-spin versions but also minimizes cost to achieve a faster time-tomarket.

The Mission of SIL is as follows.

- Ensure high-speed signal quality.
- Reduce PCB turn-around time to fix SI, PI and
- EMC issue in advance.
 - Minimize cost on board design (size, layer
- ■no.,stackup, etc).
 - Provide board stack-up design and PCB
- material selection.
 - Export layout guidelines of high-speed signals.
- Signal validation and correlation.
- Sharing SI/PI/EMI knowledge know-how with part- ners by design collaboration.



For better collaboration design with customers, we adopt world leading simulation tools in the industry field. Such as

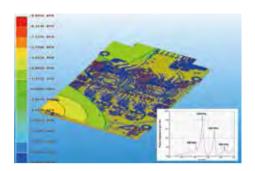
Ansys (Ansoft) Siwave 5.0

- 1. Hybrid 2D Full Wave EM Field Solver.
- 2. Analyze entire PCB and IC packages.
- 3. ID signal and power integrity problems.



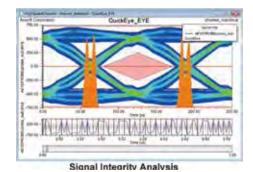
Ansys (Ansoft) PI Advisor

- 1. Optimizes power distribution
- 2. Quickly determines the optimal capacitors
- 3. Minimizes production costs, non-recurring engineering costs, and time to market.



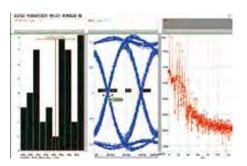
Ansys (Ansoft) Designer SI 6.0

- 1. Leverages multiple signal integrity simulation methods.
- Utilizes optimization algorithms, Design of Experiments, tuning and post-processing forkey comp.
- 3. Utilizes electromagnetic simulation and circuit tools.



Synopsys HSPICE

- 1. Uses the Gold Standard for accurate circuit simulation.
- 2. Provides Yield-Process variability and device reliability simulation.
- 3. Applies high speed simulation with harmonic balance and shooting algorithms.

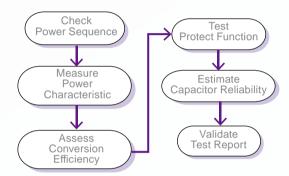


Power & energy, stable & efficient

Power Lab

Since the development of the Industrial PC it has been widely used in communications, medical, aerospace, automation & control applications and more. The power design quality and reliability is very important during product development which may affect the system operation stability and power efficiency consumption. The role of the Power Lab is to help engineers verify the power sequence, measure heat loss, etc. in order to improve the power design.

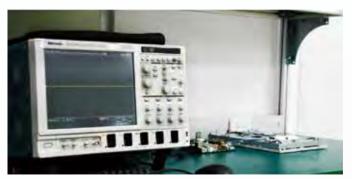
Power Validation Flow



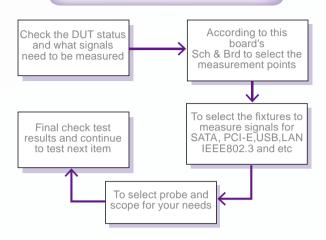


Electronic R&D Lab

The Electronic R&D Lab fulfills hardware engineers' needs by utilizing different measurement equipment which help investigate high speed signals required in Data Quality Assurance (DQA) during the test stage to ensure all hardware functionalities are compliant with the design guide.



Engineering Validation Flow



On / Off Lab

ON/OFF Lab is built to ensure our products are designed with the highest quality. By testing On and Off we can validate the system power sequence which is one of the most important test methods to ensure the reliability and compatibility.

Portwell's On/Off Lab features replay equipment that monitors power input for boards or systems and provides advanced remote control so engineers can monitor the test status of 16 systems via WAN, LAN or the Internet which proves to be an efficient method during project development.



Our modules are resistant to rapidly changing electrical currents



Electromagnetic interference (also called radio frequency interference or RFI) is a disturbance that affects an electrical circuit due to either electromagnetic induction or electromagnetic radiation emitted from an external source. The disturbance may interrupt, obstruct, or otherwise degrade or limit the effective performance of the circuit. The source may be any object, artificial or natural, that carries rapidly changing electrical currents. Problems with EMI can be minimized by ensuring that all electronic equipment is operated with a good electrical ground system. In addition, cords and cables connecting the peripherals in an electronic or computer system should be shielded

to keep unwanted RF energy from entering or leaving. Specialized components such as line filters, capacitors, and inductors can be installed in power cords and interconnecting cables to reduce the EMI susceptibility of some systems.

Placing a large amount of electrical and electronic systems into a very confined space poses the issue of keeping the EMI of these systems from interfering with each other through radiated and conducted emissions. With most systems now fully electronic, the need to contain EMI is more vital than ever starting from the design stage.

Features of Portwell EMI LAB



The EMI test receiver we utilize combines two instruments into one; measuring EMC disturbances in accordance with the latest standards and also serving as a full-featured spectrum analyzer for diverse lab applications.

Key Features

- Frequency range from 9 kHz to 3 GHz covering almost all commercial EMC standards.
 - First-ever combination of an EMI test receiver
- and spectrum analyzer in the economy class. All major functions of an advanced EMI test receiver, including fully automated test
- sequences.
- Weighting detectors: max./min. peak, average, RMS, quasi-peak as well as average with meter
- time constant and rms average in accordance with the latest version of CISPR 16-1-1

Our modules compliants with EMS standards

EMS

EMS tests including CS & RS are the reliability tests against electric fields, magnetic fields, power cords, control cables, signal cables, ground interference and static electricity discharges, electricity discharge and electromagnetic wave.

ESD

Electrostatic discharge (ESD) is the sudden and momentary electric current that flows between two objects at different electrical potentials. One of the causes of ESD events is static electricity. A system will suffer permanent damage when static electricity is generated through turbo-charging or electrostatic induction that occurs when an electrically charged object is placed near a conductive object isolated from grounding.

Features of Portwell ESD Facility

- Meets the requirements in EN/IEC 61000-4-2.
- Up to 30KV output in both contact and air discharges.
 A lightweight discharge gun.
- Easily changeable capacitor and resistor units.
- Self-explanatory control panel.
- Optional remote control Windows software offers
- more comprehensive control than local operation.





SURGE:

Surge test generates a sudden rise in power to simulate the effect of lightning shock to the power system. Utilizing this test ensures self-protection and also determines weaknesses during sudden power surges.

*Compliance with IEC 61000-4-5 SURGE 4.1KV / 2KA and 61000-4-9 (Magnetic field SURGE)



DIPS:

Dips simulates sudden drops in power and measures the immunity of products to such power interferences. This test allows us to improve upon design flaws by measuring the sustainability to such power drops.

*Compliance with IEC 61000-4-11 DIPS / VARIATION, IEC 61000-4-8 (50/60 Hz Magnetic field 50A/m) with the additional MF1000-1 antenna (1x1m)



Electrical Fast Transient (EFT) or Burst:

Every On/Off action with electronic devices generates interference to the whole power system. EFT simulates these possible circumstances to examine the immunity of an operating system in order to make improvements.

*Compliance with IEC 61000-4-4 EFT 4.4KV



4

Conducted Susceptibility Test System (CST)

The CS test examines the immunity in terms of conduction. By sending a high frequency signal, it simulates interference to test the immunity of the power core or signal. By utilizing different voltage level settings, weak points can be determined for design correction.

*Compliance with IEC/EN 61000-4-6 (IEC-Frequency range from 150 kHz ~ 80MHz)



Conducted Immunity Test System (CIT)

Conducted Immunity tests are performed to determine the ability of a device to withstand the presence of RF signals on the cables or power cords attached to the device.

*Compliance with IEC/EN 61000-4-6

A farm of chambers for module testing



The environmental test is a very important certification to all industrial products needed for mission critical environments. At Portwell, we test all our products, developed or integrated, against these conditions. Our readily available equipment always allows us to meet customer deadlines and provide detailed test results compliant with industrial standards. While there are many applications and choices in the ever-changing IPC industry, Portwell is the most competent and qualified to adapt to these changes and remain as an industrial leader. Though the quantity scale is a concern of our customers, advanced functionalities

satisfies them due to the savings of cost and time. For example, a remote monitoring system enables our customers to conduct environmental tests by way of our equipment. Meanwhile, our experienced engineers can effortlessly help our customers achieve desired results without additional costs.

Features of Portwell Chamber Zone

As a leading worldwide industrial platform provider, we know the importance of environmental testing. We build our Chamber Zones with the following features.

- Scalable More than 30 chamber devices can be installed in the zone.
- Independent Well controlled and separated space for each individual chamber in order to sustain steady operations and security of a project.

Advanced - 30 check points for every tested object to

- collect detailed data.
 - Green we recycle and use well-filled water for the
- environmental test.
 - Remote Control & Monitoring
- Manipulation of chambers and testing objects
- Allows instant acquisition of the testing data

IEC 68-2-X Certification

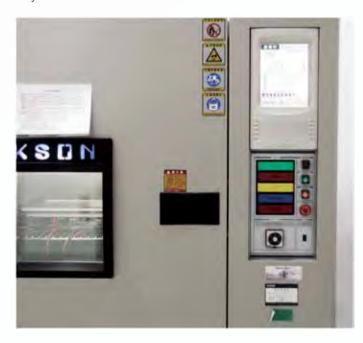
| IEC 68-2-1 | Low-temp. Test, 60°C, 96 hrs | IEC 68-2-3 | Humidity Test, 40°C, 93+2/-3% R.H., 96 hrs |
|------------|--------------------------------|-------------|--|
| IEC 68-2-2 | High-temp. Test, -10°C, 96 hrs | IEC 68-2-14 | Temp. cycle Test, -10°C ~ 60°C, 48 hrs |



Bringing thermal validation expertise to module development

Programmable Temperature & Humidity Chamber

Portwell's Programmable Temperature and Humidity Chamber Farm houses 12 programmable constant temperature and humidity testing machines, with the abilities to run from -60°C up to 150°C. Moreover, the air flow control is compliant with IEC 68-2 standard. Portwell vigorously applies these extreme conditions to their products in order to ensure their durability and accuracy while under such conditions. Therefore, Portwell can assure their customers superior and stable performance in any environment.



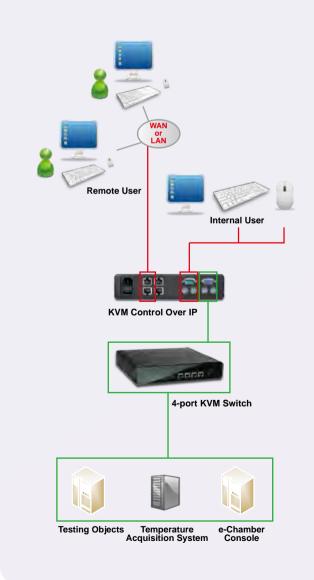
Features:

- Air Flow Control Comply with IEC 68-2 standard, lower wind is under 0.5m/s.
- With/without Due Available upon request.
- Humidity Control Can be controlled under 40°C / 10% RH.
- Web Monitoring Can be arranged by the dedicated program.

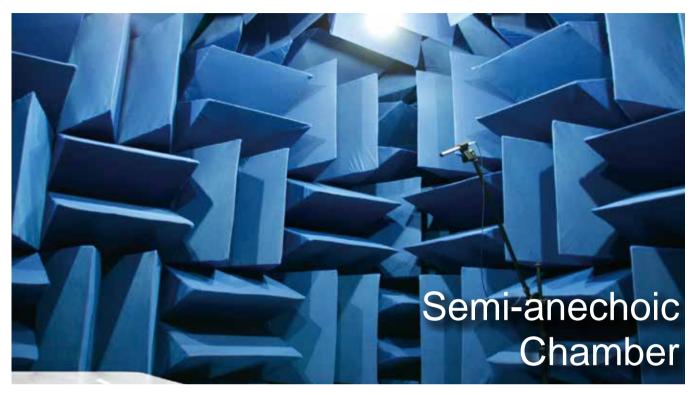
Web Monitoring Console

In order to serve those customers unable to stay at our facility for the environmental test, Portwell developed web-based tests to meet the customer demands via the internet by remote control access.

Provide us with your testing object and our engineers will arrange your object in an assigned chamber and set the remote control console with you. This service allows you to manage your tests right from your computer.



Silence is a signature of our modules



Anechoic chambers are commonly used in acoustics to conduct experiments in nominally "free field" condi- tions. All sound energy will be traveling away from the source with almost none reflected back. Common anechoic chamber experiments include measuring the transfer function of a loudspeaker or the directivity of noise radiation from industrial machinery. In general, the interior of an anechoic chamber is very quiet, with typical noise levels in the 10–20 dBA range. Full anechoic chambers aim to absorb energy in all directions. Semi-anechoic chambers have a solid

floor that acts as a work surface for supporting heavy items, such as cars, washing machines, or industrial machinery, rather than the mesh floor grille over absorbent tiles found in full anechoic chambers. This floor is damped and floating on absorbent buffers to isolate it from outside vibration or electromagnetic signals. A recording studio may utilize a semi-anechoic chamber to produce high-quality music, free of outside noise and unwanted echoes.



| Semi-anechoic Room |
|--|
| 3.95 x 3.95 x 2.5 (m2) |
| Floating Ground with Zin plated steel |
| Polymer Absorption wedge |
| Fully sealed Pressure Door, Outdoor Open, lock inside |
| ISO 3745 |
| 1kW 110V |
| Belden |
| CRAS Micophone, IEA, analyer and system. |
| |

| Chamber Type | 1/3 Octave Band Frequency(Hz) | Tolerance (dB) |
|--------------------------|-----------------------------------|-------------------------|
| Anechoic Chamber | ≤ 630 800-5,000 ≥6,300 | ± 1.5 ± 1.0 ± 1.5 |
| Semi-Anechoic Chamber | ≤ 630 800-5,000 ≥6,300 | ± 2.5 ± 2.0 ± 2.5 |

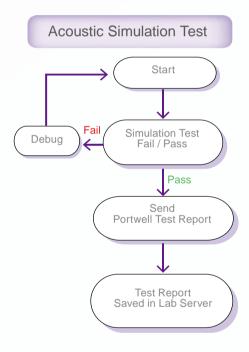
The noise emission meet ISO Standards

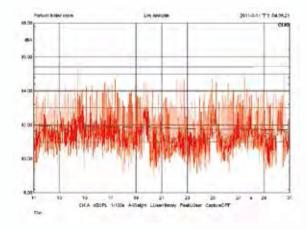
Goals of Semi-Acoustic Chamber

In Portwell Semi-Acoustic Chamber we follow the simulation procedure demonstrated below to validate our system noise levels. Our method is to provide dimension, space, wedged material, placement of EUT and microphones in the chamber in accordance with ISO 7779 standards which help us verify that the noise levels of our products fall within universal criteria.

Our goals are:

- Ensure medical related products can comply with noise requirements.
- Service customer to verify their products can meet local noise standards.

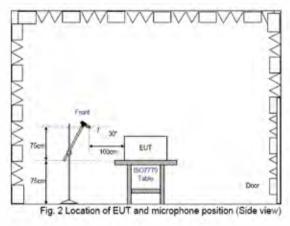




Portwell semi-acoustic chamber is based on ISO 3745 which states that indoor background noise remain under 15dB(A) while outside noise is under or equal to 70dB(A); thus we can detect accurate results for product evaluation.

ISO 3745:1977

Specifies two laboratory methods. First, it establishes requirements for the test room as well as the source location, operating conditions and instrumentation. Secondly, it specifies techniques for obtaining an estimate of the surface sound pressure level from which the weighted sound power level of the source and the sound power level in octave or one-third octave bands may be calculated.



All the dimensions, space, material of wedges, placement of EUT and microphone within our semi-acoustic chamber follow ISO 7779 standards which ensure our products meet universal criteria.

ISO 3745:1977

ISO 7779:2010 specifies procedures for measuring and reporting the noise emission of information technology and telecommunications equipment The basic emission quantity is the A-weighted sound power level which may be used for comparing equipment of the same type but from different manufacturers, or for comparing different equipment. Portwell Semi-A coustic Chamber follows ISO 7779 when determining sound power levels of a machine.

Breaking the module to be stronger



A Highly Accelerated Life Test (HALT), is a stress testing methodology for accelerating product reliability during the engineering development process. It is commonly performed to identify and help resolve design weaknesses with progressively more severe environmental stresses. Another feature of HALT testing is that it characterizes the equipment under stress, and identifies the equipment's safe operating limits and design margins. Some common forms of failure acceleration for industrial products are power cycling, temperature cycling and random vibration. HALT serves to improve the reliability of a product and is an empirical method used to identify the limiting failure and the stresses at which these failures occur.

The major advantages of HALT are: a) it can be conducted during the development phase of a product in order to weed out design problems and marginal components thereby eliminating costs for warranty returns; b) it also is conducted as internal qualification testing which significantly reduce costs prior to sending the equipment for formal qualification.

During a HALT test the tested equipment has to be functional and operational while monitored so that if the equipment fails while being stressed, the failure will be detected. The failure may only

Typhoon 4.0

UPPER TABLE POSITION :

WORK SPACE 53.8"w x 54"d x 34.6"h (1366 x 1372 x 879mm)

LOWER TABLE POSITION: 53.8"w x 54"d x 53.6"h (1366 x 1372 x 1362mm)

OUTER 69.2"w x 78.8"d x 103.9"h

DIMENSIONS (1759 x 2003 x 2640mm)

TEMPERATURE +200 °C TO -100 °C, +250 °C TO -100 °C

THERMAL RAMP 70 °C - 100 °C/min average

TABLE SIZE 48" x 48" (1220 x 1220mm)

5 - 75 gRMS (Bare Table)
TABLE CAPACITY 600 lbs (272kg)

Recommended

TABLE CAPACITY
600 lbs (272kg)
Recommended

POWER REQUIREMENTS380V, 400V, 440V, 480V, 3φ, 50/60Hz, 100A

ACTUATORS 12 Lubricant free

be present while the stress is applied and may not cause permanent degradation that would be apparent after the stress is removed. All failures during HALT testing are subject to failure analysis and root cause analysis.

Super-aging our modules to unveil weaknesses



Stresses are delivered in an ordered sequence:

- Temperature Step Stress
 - 1. Cold Step Stress
 - 2. Hot Step Stress
- Rapid Temperature Transition Cycling
- Vibration Step Stress
- Combined Environment
 - 1. Rapid Temperature Transition Cycling and
 - 2. Vibration Step Stress

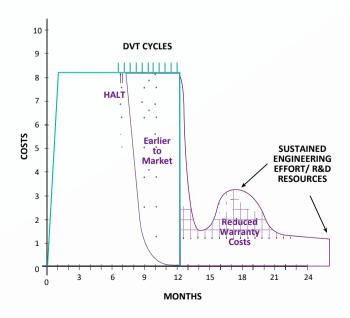
Portwell chooses a Typhoon 4.0 system which is designed specifically for the task of performing Highly Accelerated Stress Screening (HASS) and HALT on large products. With the Lowest Total Cost of Ownership within the AST industry, the 48" x 48" vibration table is capable of supporting hundreds of pounds of products and fixtures, while delivering low frequency ranges necessary to induce failure. For high temperature applications in simulating harsh conditions, this system is available as the InfernoTM which can deliver temperatures up to 250°C.

When validating the HALT test we follow the step by step procedure which helps us to analyze time of failures so that our engineers can make the necessary revisions.



Features of Portwell HALT Lab

- Increase Product Reliability
- Reduce Design Verification Time and Expense Remove Costly Manufacturing Defects
- Reduce Warranty Costs
- Increase Sales Revenues with Reputation for Quality



Undergo shipping simulation to ensure intact transportation

Vibration

Vibration is capable of damaging electronic components and component soldering. In our Vibration Chamber, we simulate variable vibration conditions that could potentially damage our products during their transportation, installation or operation. Therefore we rigorously test every product and gather accurate statistical analysis as proof of the outstanding level of tolerance and endurance in every Portwell product.

Vibration tester conducts either Sine or Random vibration.

Sine Vibration complies with IEC-68-2-6 and simulates the product on a ship to verify Resonance Search and Resonance Dwell. Random Vibration complies with IEC-68-2-36 and simulates the product in transportation situations in order to test the packaged product's vibration endurance.



* Compliance with IEC-68 Comply the IEC-68 environ mental regulation. The max magnetic force is 1000kgF.

Shock

The test purpose is to evaluate whether the limit of the products' strength is consistent with those in the product line. When the tested item is shocked and the mechanically fragile part is found, mechanical R&D engineers can amend the supporting structure and analyze the properties of material to effectively prevent possible damage in the future.

The tested item is unpackaged. Three-axis & 6-face (each face tested 3 times) should be conducted to pass specified shock conditions of 15G peak acceleration and a pulse duration for 11 ms. (3 times for each face under operation condition)

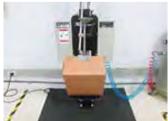


* Compliance with IEC-68.

Drop

This test focuses on package design. The drop test is conducted in order to test whether the packaged product remains intact and 100% functional after being dropped. This test simulates the accidents that occur during shipping and handling. Therefore, we also focus on the design of our packages to ensure you receive the product as if it just came off the shelf.







* Complies with IEC-68.

Portwell superior service

Completed Technical Service

In order to ensure customers receive fast and appropriate service from Portwell, we offer the following services to meet your needs.



Logistics Service

It is not only for the scalable or worldgrade customers, we offer the service to our partners who need the world-wide delivery to save time and expense.



Consulting Service

Our engineering experts provide a free service to discuss with you the projects or technologies that you need in a short period of time. Please visit Portwell web and click the button, then the on-line service will appear for you.



Product Service

We have the experienced product managers who can help you to get the right products in our list and also the related information to complete your solution.



Portwell has the most advanced manufacturing facilities to produce the quality product for your application or business. Please pay a visit to our Portwell engine, you will know how best that we can do for you.



Design Service

If our existing products cannot meet your requirements, a customized design service can be initiated to build the exact products that you demand.

Both Portwell RDC & SIC are prepared for complete service to our customers & partners. Should you have any requirements or technical issues, please contact us. Our services can be arranged in the following ways.

Web Service

Please visit us on the web and leave a message. We also provide an on-line consulting service via Skype. And if immediate assistance is needed, contact us by phone.

Extended Visits to PE

Sometimes it is difficult to find the solution in a short period of time. Therefore, Portwell provides a dormitory for our customers and partners to stay until we reach the necessary solutions. Please contact us and our staff will arrange a place for you to stay.

Direct Contact

Portwell welcomes our customers to visit our laboratory to witness our regulation tests and design service. This is the best way to answer all your questions and help you find the right solution.



Live Chat (Skype)

You can get the on-line consulting service via Skype if an immediate response is needed. http://www.portwell.com.tw/support/LiveChat.php



Global Service (Telephone)

In addition, you can get immediate support via telephone. Check the web site for phone numbers.

http://www.portwell.com.tw/contact/worldwide.html



E-Mail

Portwell's technical support department can be reached by e-mail as follows

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